

Features

- Operating voltage: 2.4V~5.2V
- Bidirectional I/O lines with a selection of 18, 22, 32 and 56 lines
- One interrupt input
- Programmable timer/event counters with overflow interrupts and a selection of one 8-bit counter, one 8-bit and one 16-bit counters, or two 16-bit counters
- On-chip crystal and RC oscillator
- Watchdog timer
- Program ROM with size selection of 1K×14, 2K×14, 4K×15 and 8K×16 bits
- Data RAM with size selection of 64×8, 96×8, 160×8 and 224×8 bits
- Halt function and wake-up feature to reduce power consumption
- 63 powerful instructions
- Up to 0.5μs instruction cycle with 8MHz system clock at V_{DD}=5V
- All instructions in 1 or 2 machine cycles
- 14-bit/15-bit/16-bit table read instructions
- 2-level/4-level/8-level subroutine nesting
- Bit manipulation instructions

General Description

The HT48C10/48C30/48C50/48C70 are 8-bit high performance RISC-like microcontrollers, specifically designed for multiple I/O product applications. These devices are suitable for use in products such as remote controllers, fan/light controllers, washing machine controllers, scales, toys, and various subsystem controllers. They all contain a halt feature to reduce power consumption. The major differences between

these microcontrollers are attributed to variations in sizes of the ROM and RAM, as well as bit number, counter number, I/O line number, and different level subroutine nesting. Roughly speaking, the HT48C10 is a microcontroller with most economic features and the HT48C70 is one with the most features of the four microcontrollers.

Selection Table

Mask version

Part No.	HT48C10	HT48C30	HT48C50	HT48C70
Operating Voltage	2.4V~5.2V	2.4V~5.2V	2.4V~5.2V	2.4V~5.2V
External Interrupt	1	1	1	1
Internal Interrupt	1	1	2	2
8-bit Timer/Event Counter	1	1	1	0
16-bit Timer/Event Counter	0	0	1	2
System Oscillator	Crystal/RC	Crystal/RC	Crystal/RC	Crystal/RC
Watchdog Timer	1	1	1	1
ROM	1K×14	2K×14	4K×15	8K×16
RAM	64×8 (40H~7FH)	96×8 (20H~7FH)	160×8 (60H~FFH)	224×8 (20H~FFH)
I/O Lines	18	22	32	56
Instructions	63	63	63	63
Stack Levels	2	2	4	8
Operating Frequency	400kHz~8MHz	400kHz~8MHz	400kHz~8MHz	400kHz~8MHz
Power Down Mode	√	√	√	√
Table Read Instructions	√	√	√	√

OTP version

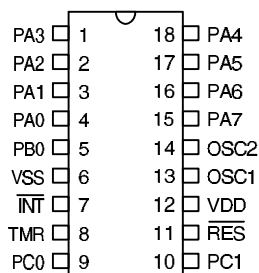
Part No.	V _{DD}	f _{sys}	I/O Pull-high	Mask version
HT48R11	3.0V~5.2V	400k~4MHz	No	HT48C10
HT48R12	3.0V~5.2V	400k~4MHz	Yes	HT48C10
HT48R31	3.0V~5.2V	400k~4MHz	No	HT48C30
HT48R32	3.0V~5.2V	400k~4MHz	Yes	HT48C30
HT48R50	3.0V~5.2V	400k~4MHz	Yes	HT48C50
HT48R51*	3.0V~5.2V	400k~4MHz	No	HT48C50

* Under development

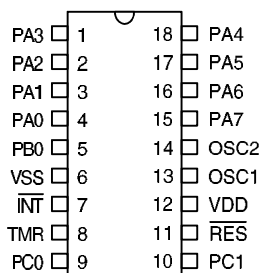
The block diagram illustrates the internal architecture of the ATmega16 microcontroller. Key components include:

- Program Memory:** Program ROM and Program Counter.
- Instruction Path:** Instruction Register, Instruction Decoder, and Timing Generator (driven by OSC1 and OSC2).
- Data Path:** Data Memory, ALU, Shifter, and ACC (Accumulator).
- Stack:** STACK0 through STACK7.
- Interrupts:** Interrupt Circuit and INTC (Interrupt Control and Flag Register).
- Timers/Counters:** TMR0, TMR0C, TMR1, TMR1C, and WDT (Watchdog Timer) with WDT Prescaler.
- Ports:** PORT A through PORT G, each with corresponding data registers (PA, PB, PC, PD, PE, PF, PG) and pull-up resistors.
- Other Features:** RC OSC (Resettable Constant Oscillator), MUX (Multiplexers), and various control signals like INT, INTX, and TMR0/TMR1 flags.

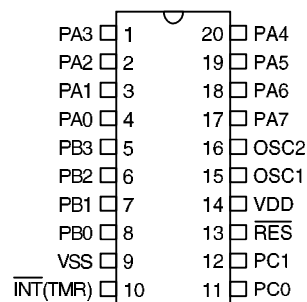
Pin Assignment



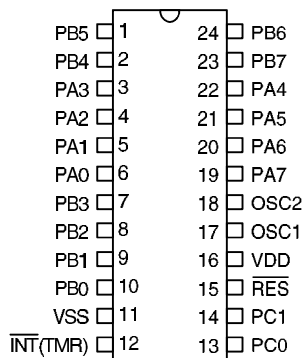
HT48C10
– 18 DIP-F



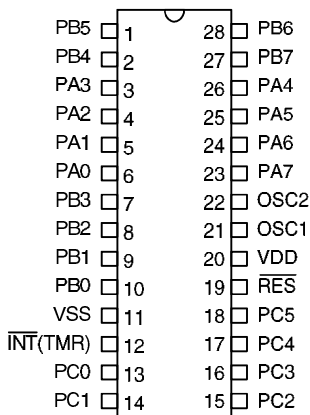
HT48C30
– 18 DIP-A



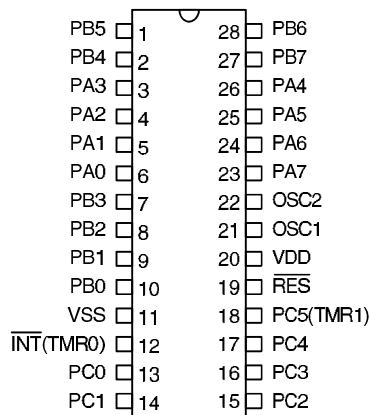
HT48C10/HT48C30
– 20 DIP-F/SOP-F



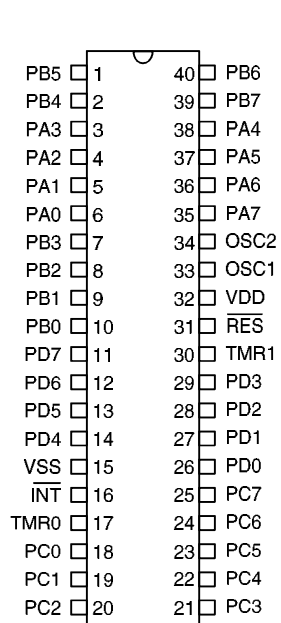
HT48C10
– 24 SKDIP-B



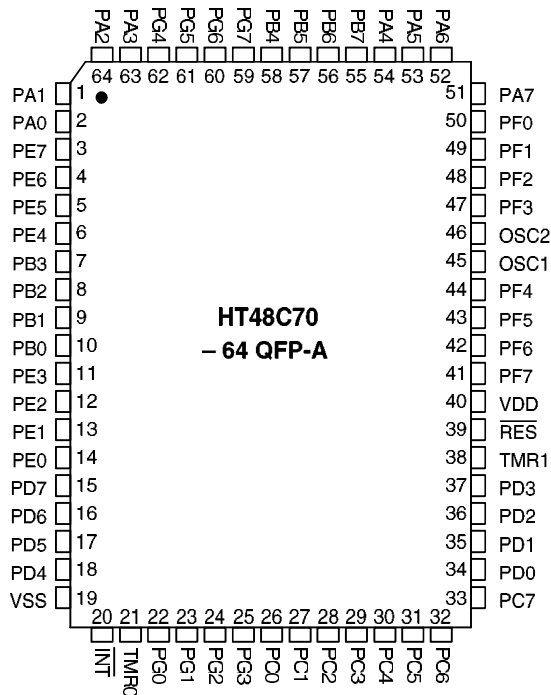
HT48C30
– 28 SKDIP-B



HT48C50
– 28 SKDIP-B



HT48C50/HT48C70
– 40 DIP-A



Note: For the dice form, the TMR0 and TMR1 pads have to be bonded to VDD or VSS if the TMR0 and/or TMR1 pad are not used.

The (TMR0) INT indicates that the TMR0 pad should be bonded to the INT pin.

The PC5 (TMR1) indicates that the TMR1 pad should be bonded to the PC5 pin.

Pin Description of HT48C10

Pin Name	I/O	Mask Option	Function
PA0~PA7	I/O	Wake-up Pull-high or None	Bidirectional 8-bit input/output ports Each bit can be configured as a wake-up input by mask option. Software instructions determine the CMOS output or schmitt trigger input with or without pull high resistor (by mask option).
PB0~PB7	I/O	Pull-high or None	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without pull high resistor (by mask option).
VSS	—	—	Negative power supply, GND
$\overline{\text{INT}}$	I	—	External interrupt schmitt trigger input with pull high resistor Edge trigger is activated during high to low transition.
TMR	I	—	Schmitt trigger input for timer/event counter
PC0~PC1	I/O	Pull-high or None	Bidirectional 2-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without pull high resistor (by mask option).
$\overline{\text{RES}}$	I	—	Schmitt trigger reset input, active low
VDD	—	—	Positive power supply
OSC1 OSC2	I O	Crystal or RC	OSC1 and OSC2 are connected to an RC network or a crystal (by mask option) for the internal system clock. In the case of RC operation, OSC2 is the output terminal for 1/4 system clock.

Pin Description of HT48C30

Pin Name	I/O	Mask Option	Function
PA0~PA7	I/O	Wake-up Pull-high or None	Bidirectional 8-bit input/output ports Each bit can be configured as a wake-up input by mask option. Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
PB0~PB7	I/O	Pull-high or None	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
VSS	—	—	Negative power supply, GND
$\overline{\text{INT}}$	I	—	External interrupt schmitt trigger input with a pull high resistor. Edge triggered is activated on a high to low transition.
TMR	I	—	Schmitt trigger input for timer/event counter
PC0~PC5	I/O	Pull-high or None	Bidirectional 6-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
$\overline{\text{RES}}$	I	—	Schmitt trigger reset input, active low
VDD	—	—	Positive power supply
OSC1 OSC2	I O	Crystal or RC	OSC1 and OSC2 are connected to an RC network or a crystal (by mask option) for the internal system clock. In the case of RC operation, OSC2 is the output terminal for 1/4 system clock.

Pin Description of HT48C50

Pin Name	I/O	Mask Option	Function
PA0~PA7	I/O	Wake-up Pull-high or None	Bidirectional 8-bit input/output ports Each bit can be configured as a wake-up input by mask option. Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
PB0~PB7	I/O	Pull-high or None	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
VSS	—	—	Negative power supply, GND
$\overline{\text{INT}}$	I	—	External interrupt schmitt trigger input with a pull high resistor. Edge triggered is activated on a high to low transition.
TMR0	I	—	Schmitt trigger input for timer/event counter 0
TMR1	I	—	Schmitt trigger input for timer/event counter 1
PC0~PC7	I/O	Pull-high or None	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
$\overline{\text{RES}}$	I	—	Schmitt trigger reset input, active low
VDD	—	—	Positive power supply
OSC1 OSC2	I O	Crystal or RC	OSC1 and OSC2 are connected to an RC network or a crystal (by mask option) for the internal system clock. In the case of RC operation, OSC2 is the output terminal for 1/4 system clock.
PD0~PD7	I/O	Pull-high or None	Bidirectional 8-bit Input/Output port. Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).

Pin Description of HT48C70

Pin Name	I/O	Mask Option	Function
PA0~PA7	I/O	Wake-up Pull-high or None	Bidirectional 8-bit input/output ports Each bit can be configured as a wake-up input by mask option. Software instructions determine the CMOS output or schmitt trigger input with or without pull high resistor (by mask option).
PB0~PB7	I/O	Pull-high or None	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).
VSS	—	—	Negative power supply, GND
$\overline{\text{INT}}$	I	—	External interrupt schmitt trigger with pull high resistor Edge trigger is activated during high to low transition.
TMR0	I	—	Schmitt trigger input for timer/event counter 0
TMR1	I	—	Schmitt trigger input for timer/event counter 1
PC0~PC7	I/O	Pull-high or None	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).
$\overline{\text{RES}}$	I	—	Schmitt trigger reset input, active low
VDD	—	—	Positive power supply
OSC1 OSC2	I O	Crystal or RC	OSC1 and OSC2 are connected to an RC network or a crystal (by mask option) for the internal system clock. In the case of RC operation, OSC2 is the output terminal for 1/4 system clock.
PD0~PD7	I/O	Pull-high or None	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).
PE0~PE7	I/O	Pull-high or None	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).
PF0~PF7	I/O	Pull-high or None	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).
PG0~PG7	I/O	Pull-high or None	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).

Absolute Maximum Ratings

Supply Voltage	V_{DD} –0.3V to 5.5V	Storage Temperature.....	–50°C to 125°C
Input Voltage	V_{SS} –0.3V to V_{DD} +0.3V	Operating Temperature	–25°C to 70°C

Note: These are stress ratings only. Stresses exceeding the range specified under “Absolute Maximum Ratings” may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

D.C. Characteristics

$T_a=25^{\circ}\text{C}$

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DD}	Operating Voltage	—	—	2.4	—	5.2	V
I_{DD1}	Operating Current (HT48C10 Crystal OSC)	3V	No load	—	0.7	1.5	mA
		5V	$f_{SYS}=4\text{MHz}$	—	2	3	
I_{DD2}	Operating Current (HT48C10 RC OSC)	3V	No load	—	0.5	1	mA
		5V	$f_{SYS}=2\text{MHz}$	—	1	2	
I_{DD3}	Operating Current (HT48C30 Crystal OSC)	3V	No load	—	0.7	1.5	mA
		5V	$f_{SYS}=4\text{MHz}$	—	2	3	
I_{DD4}	Operating Current (HT48C30 RC OSC)	3V	No load	—	0.5	1	mA
		5V	$f_{SYS}=2\text{MHz}$	—	1	2	
I_{DD5}	Operating Current (HT48C50 Crystal OSC)	3V	No load	—	1	2	mA
		5V	$f_{SYS}=4\text{MHz}$	—	2.5	5	
I_{DD6}	Operating Current (HT48C50 RC OSC)	3V	No load	—	0.75	1.5	mA
		5V	$f_{SYS}=2\text{MHz}$	—	1.5	3	
I_{DD7}	Operating Current (HT48C70 Crystal OSC)	3V	No load	—	1.5	3	mA
		5V	$f_{SYS}=4\text{MHz}$	—	3.4	6	
I_{DD8}	Operating Current (HT48C70 RC OSC)	3V	No load	—	1	2	mA
		5V	$f_{SYS}=2\text{MHz}$	—	2.1	4	
I_{STB1}	Standby Current (WDT Enabled)	3V	No load	—	—	5	μA
		5V	system halt	—	—	10	
I_{STB2}	Standby Current (WDT Disabled)	3V	No load	—	—	1	μA
		5V	system halt	—	—	2	

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{IL}	Input Low Voltage for I/O ports	3V	—	0	—	0.9	V
		5V	—	0	—	1.5	
V _{IH}	Input High Voltage for I/O Ports	3V	—	2.1	—	3	V
		5V	—	3.5	—	5	
V _{IL1}	Input Low Voltage (TMR, TMR0, TMR1, INT)	3V	—	0	—	0.7	V
		5V	—	0	—	1.3	
V _{IH1}	Input High Voltage (TMR, TMR0, TMR1, INT)	3V	—	2.3	—	3	V
		5V	—	3.8	—	5	
V _{IL2}	Input Low Voltage ($\overline{\text{RES}}$)	3V	—	—	1.5	—	V
		5V	—	—	2.5	—	
V _{IH2}	Input High Voltage ($\overline{\text{RES}}$)	3V	—	—	2.4	—	V
		5V	—	—	4.0	—	
I _{OL}	I/O Ports Sink Current	3V	V _{OL} =0.3V	1.5	4	—	mA
		5V	V _{OL} =0.5V	4	10	—	
I _{OH}	I/O Ports Source Current	3V	V _{OH} =2.7V	−1	−2	—	mA
		5V	V _{OH} =4.5V	−2	−4.5	—	
R _{PH}	Pull-high Resistance of I/O Ports and INT	3V	—	40	60	80	kΩ
		5V	—	10	30	50	

A.C. Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
f _{SYS1}	System Clock (Crystal OSC)	3V	—	400	—	4000	kHz
		5V	—	400	—	8000	kHz
f _{SYS2}	System Clock (RC OSC)	3V	—	400	—	2000	kHz
		5V	—	400	—	3000	kHz
f _{TIMER}	Timer I/P Frequency (TMR, TMR0, TMR1)	3V	—	0	—	4000	kHz
		5V	—	0	—	4000	kHz
t _{WDTOSC}	Watchdog Oscillator	—	—	45	90	180	μs
				35	65	130	
t _{WDT1}	Watchdog Time-out Period (RC)	—	Without WDT prescaler	12	23	45	ms
				9	17	35	
t _{WDT2}	Watchdog Time-out Period (System Clock)	—	Without WDT prescaler	—	1024	—	t _{sys}
t _{RES}	External Reset Low Pulse Width	—	—	1	—	—	μs
t _{SST}	System Start-up Timer Period	—	Power-up or Wake-up from halt	—	1024	—	t _{sys}
t _{INT}	Interrupt Pulse Width	—	—	1	—	—	μs

Note: t_{sys}=1/f_{sys}

Functional Description

The four microcontrollers of the HT48C10/HT48C30/HT48C50/HT48C70 are constructed using basically the same principles. Their differences lie in variations in sizes such as ROM and RAM as well as bit number, counter number, I/O line number, and different level subroutine nesting bit number. The following is a more detailed description of the system architectures of the four microcontrollers. Unless specified, the architecture stated below exists in these four microcontrollers.

Execution flow

The system clock is derived from either a crystal or an RC oscillator. It is internally divided into four non-overlapping clocks. Each instruction cycle consists of four system clock cycles.

Instruction fetching and execution are pipelined in such a way that a fetch takes one instruction cycle while decoding and execution takes the next instruction cycle. The pipelining scheme causes each instruction to effectively execute in a cycle. If an instruction changes the program counter, two cycles are required to complete the instruction.

Program counter – PC

The program counter (PC) is of different sizes ranging from 10 bits to 13 bits according to the microcontroller selected (10 bits for the HT48C10; 11 bits for the HT48C30; 12 bits for the HT48C50; 13 bits for the HT48C70). It con-

trols a sequence in which the instructions stored in the program ROM are executed. The contents of the PC can specify 1024, 2048, 4096, or 8192 addresses at maximum, according to the microcontroller (HT48C10/HT48C30/HT48C50/HT48C70) chosen.

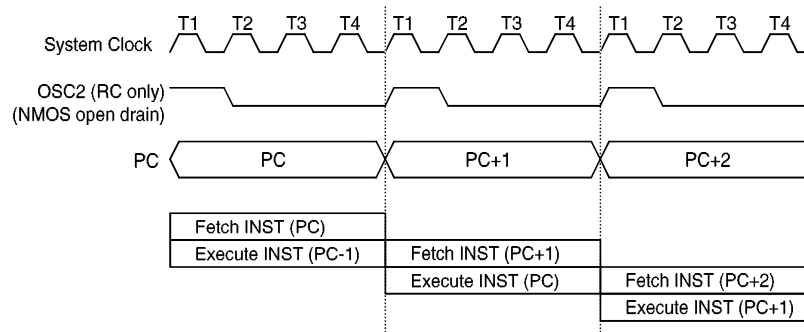
After accessing a program memory word in order to fetch an instruction code, the contents of the PC is incremented by one. The PC then points to the memory word consisting of the next instruction code.

When executing a jump instruction, conditional skip execution, loading a PCL register, a subroutine call, an initial reset, an internal interrupt, an external interrupt, or returning from a subroutine, the PC manipulates a program transfer by loading the address corresponding to each instruction.

The conditional skip is activated by instructions. Once the condition is met, the next instruction, fetched during the current instruction execution, is discarded and a dummy cycle replaces it to get a proper instruction; otherwise it proceeds to the next instruction.

The lower byte of the PC (PCL) is a readable and writeable register (06H). Moving data into the PCL performs a short jump. The destination is within 256 locations.

For a control transfer to take place, an additional dummy cycle is required.



Execution flow

Program memory – ROM

The program memory (ROM) is used to store the program instructions that are to be executed. It contains data, table, and interrupt entries, and is organized into 1024×14 bits, 2048×14 bits, 4096×15 bits, or 8192×16 bits according to the microcontroller (HT48C10/ HT48C30/HT48C50/ HT48C70) selected. These bits are all addressed by the PC and table pointer.

Certain locations in the ROM stated below are reserved for special usage in the four microcontrollers except location 00CH which is used for the HT48C50/HT48C70 exclusively.

- Location 000H

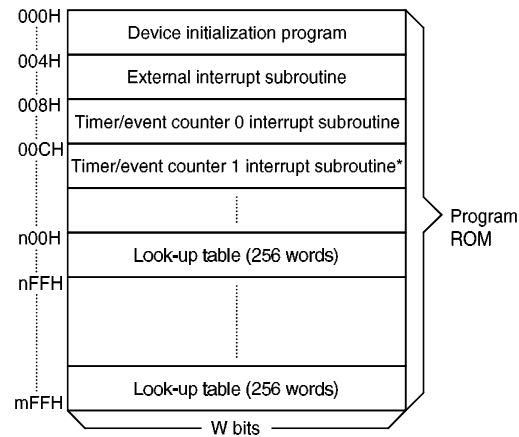
Location 000H is reserved for program initialization. After chip reset, the program always begins execution at this area.

- Location 004H

Location 004H is reserved for external interrupt service program. If the $\overline{\text{INT}}$ input pin is activated, the interrupt is enabled, and the stack is not full, the program begins execution at location 004H.

- Location 008H

Location 008H is reserved for the timer/event counter interrupt service program of the HT48C10/HT48C30 and for the timer/event counter 0 interrupt service program of the



Note:

1. n ranges from 0 to m
2. m=3 and W=14 for the HT48C10 only
m=7 and W=14 for the HT48C30 only
m=F and W=15 for the HT48C50 only
m=1F and W=16 for the HT48C70 only
3. * for the HT48C50 and HT48C70 only

Program memory

HT48C50/HT48C70. If the timer interrupt results from a timer/event counter overflow of the HT48C10/HT48C30 or a timer/event counter 0 overflow of the HT48C50/HT48C70, and the interrupt is enabled, and the stack is not full, the program begins execution at location 008H.

Mode	Contents of Program Counter (m bits)
Initial reset	0000H
External interrupt	0004H
Timer/event counter 0 overflow	0008H
Timer/event counter 1 overflow	000CH
Skip	PC+2
Loading PCL	Low byte replaced by instruction code
Jump, call branch	Instruction code
Return from subroutine	Stack register

Notes: m=10 for the HT48C10
m=11 for the HT48C30
m=12 for the HT48C50
m=13 for the HT48C70

- Location 00CH

Location 00CH is reserved for the timer/ event counter 1 interrupt service program of the HT48C50/HT48C70 only. If the timer interrupt results from a timer/event counter 1 overflow, the interrupt is enabled, and the stack is not full, the program begins execution at location 00CH.

- Table location

Any location in the ROM can be used as a look-up table. The instructions TABRDC [m] (the current page, 1 page=256 words) and TABRDL [m] (the last page) transfer the contents of the lower-order byte to the specified data memory, and the higher-order byte to TBLH (08H). Only the destination of the lower-order byte in the table is well-defined, and the higher-order byte of the table word is transferred to the Table Higher-order byte register (TBLH). The TBLH is read only. The Table Pointer (TBLP), on the other hand, is a read/write register (07H) used to indicate the table location. Before accessing the table, the location should be placed in the TBLP. The TBLH is read only and cannot be restored. If the main routine and the ISR (Interrupt Service Routine) both employ the table read instruction, the contents of the TBLH in the main routine is likely to be changed by the table read instruction used in the ISR. Errors will then occur. Hence, simultaneously using the table read instruction in the main routine and the ISR should be avoided. Nonetheless, if the application of the table read instruction

to both the main routine and the ISR cannot be avoided, interrupts should be disabled prior to the table read instruction, and they should not be enabled until the TBLH is backed-up. All the table related instructions require 2 cycles to complete an operation. These areas may function as a normal program memory depending upon the user's requirements.

Stack register – STACK

The stack register is a special memory port used to save the contents of the PC. The stack can be organized into 2, 4, or 8 levels according to the microcontroller selected (2 levels for the HT48C10/HT48C30, 4 levels for the HT48C50, 8 levels for the HT48C70). The register is neither part of the data nor part of the program, and is neither readable nor writeable. Any activated level is indexed by a stack pointer (SP) and is neither readable nor writeable. At a subroutine call or interrupt acknowledgment, the contents of the PC is pushed onto the stack. At the end of a subroutine or an interrupt routine, signaled by a return instruction (RET or RETI), the contents of the PC is restored to its previous value from the stack. After chip reset, the SP will point to the top of the stack.

If the stack is full and a non-masked interrupt takes place, the interrupt request flag is recorded but the acknowledgment is still inhibited. After the stack pointer is decremented (by RET or RETI), the interrupt will be serviced. This feature prevents the occurrence of stack overflow, allow-

Instruction(s)	Table Location								
	*m~*8	*7	*6	*5	*4	*3	*2	*1	*0
TABRDC [m]	Pm~P8	@7	@6	@5	@4	@3	@2	@1	@0
TABRDL [m]	1~1	@7	@6	@5	@4	@3	@2	@1	@0

Table location

Notes: *m~*0: Bits of table location
 @7~@0: Bits of table pointer
 Pm~P8: Bits of current
 Program Counter

m=9 for the HT48C10
 m=10 for the HT48C30
 m=11 for the HT48C50
 m=12 for the HT48C70

ing the programmer to use the structure easily. Likewise, if the stack is full and a CALL is subsequently executed, a stack overflow will occur and the first entry will be lost (only the most recent four return addresses will be stored).

Data memory – RAM

The data memory (RAM) is composed of bits ranging from 81×8, 113×8, 184×8, or 255×8, depending on the microcontroller chosen (HT48C10/ HT48C30/HT48C50/HT48C70). It is divided into two functional groups, i.e., special function registers and general purpose data memory (of 64×8, 96×8, 160×8, or 224×8 bits, depending on the microcontroller selected (HT48C10/ HT48C30/HT48C50/HT48C70). Most components of the two functional groups are readable/writable, but some are read-only.

Of the two functional groups, the special function registers of the four microcontrollers consist of a program counter lower-order byte register (PCL;06H), an accumulator (ACC;05H), a table pointer (TBLP;07H), a table higher-order byte register (TBLH;08H), a status register (STATUS;0AH), an interrupt control register (INTC;0BH), a watchdog timer option setting register (WDTS;09H), an indirect addressing register (00H), a memory pointer register (MP;01H), a timer/event counter (TMR;0DH), a timer/event counter control register (TMRC;0EH), I/O registers (PA;12H,PB;14H, PC;16H), and I/O control registers (PAC;13H,PBC;15H,PCC;17H). But of the HT48C50/HT48C70, the following components are further divided into two or several sub-components. First, the indirect addressing register is divided into two registers involving indirect addressing register 0 (00H) and indirect addressing register 1 (02H). Second, the memory pointer register is also comprised by two registers involving memory pointer register 0 (MP0;01H) and memory pointer register 1 (MP1;03H). Third, the timer/event counter register is organized by two registers according to different orders of byte, namely timer/event higher-order byte register and timer/event lower-order byte register, both of which are further divided into timer/event counter 0 higher-

00H	Indirect Addressing Register 0*
01H	MP0*
02H	Indirect Addressing Register 1***
03H	MP1***
04H	
05H	ACC*
06H	PCL*
07H	TBLP*
08H	TBLH*
09H	WDTS*
0AH	STATUS*
0BH	INTC*
0CH	TMR0H***
0DH	TMR0L*** (TMR*)
0EH	TMR0C*** (TMRC*)
0FH	TMR1H****
10H	TMR1L (TMR1)***
11H	TMR1C***
12H	PA*
13H	PAC*
14H	PB*
15H	PBC*
16H	PC*
17H	PCC*
18H	PD***
19H	PDC***
1AH	PE****
1BH	PEC****
1CH	PF****
1DH	PFC****
1EH	PG****
1FH	PGC****
...	
General Purpose Data Memory	
40H~7FH for the HT48C10	
20H~7FH for the HT48C30	
60H~FFH for the HT48C50	
20H~FFH for the HT48C70	

Special Purpose
Data Memory

□ : Unused
Read as "00"

Note:

1. * for the HT48C10~HT48C70
2. ** for the HT48C30~HT48C70 only
3. *** for the HT48C50 and HT48C70 only
4. **** for the HT48C70 only

RAM mapping

order byte register (TMR0H; 0CH), timer/ event counter 1 higher-order byte register (TMR1H;0FH), timer/event counter 0 lower-order byte register (TMR0L;0DH), and timer/event counter 1 lower-order byte register (TMR1L;10H). Fourth, the timer/event counter control register is divided into two registers involving timer/event counter 0 control register

(TMR0C;0EH) and timer/event counter 1 control register (TMR1C;11H). Fifth, the entire number of I/O registers is expanded from 3 to 6 (PA;12H,PB;14H,PC;16H,PD;18H,PE;1AH,PF;1CH,PG;1EH). Finally, the number of I/O control registers is also doubled (PAC;13H,PBC;15H,PCC;17H,PDC;19H,PEC;1BH,PFC;1DH,PGC;1FH). The remaining space before the 20H of the four microcontrollers are all reserved for future expansion usage. Reading these remaining locations will return the result to 00H. The general purpose data memory, addressed from 40H~7FH of the HT48C10, 20H~7FH of the HT48C30, 60H~FFH of the HT48C50, or 20H~FFH of the HT48C70 according to the microcontroller selected, is used for data and control information under instruction commands.

All the RAM areas can directly execute arithmetic, logic, increment, decrement, and rotate operations. Except some dedicated bits, each bit in the RAM can be set and reset by the SET [m].i and CLR [m].i instructions, respectively. These RAM areas are indirectly accessible through the memory pointer register(s) MP (01H) of the HT48C10/HT48C30 or MP0 (01H) and MP1 (03H) of the HT48C50/HT48C70.

Indirect addressing register

Of the four microcontrollers, the HT48C10/HT48C30 make use of location 00H whereas the HT48C50/HT48C70 of locations 00H and 02H as indirect addressing registers that are not physically implemented. Any read/write operation of [00H] or of [00H] and [02H] accesses the RAM pointed to by MP (01H) or by MP0 (01H) and MP1 (03H) respectively according to the microcontroller chosen. Reading location 00H or 02H indirectly will return the result 00H. Writing it indirectly will, result to no operation.

The function of data movement between two indirect addressing registers is not supported. The memory pointer register MP of the HT48C10/HT48C30 or MP0 and MP1 of the HT48C50/HT48C70 are of 7 bits or 8 bits wide respectively, and can be used to access the RAM

by combining the corresponding indirect addressing registers. The bit 7 of MP (HT48C10/HT48C30) is undefined and reading will return the result "1". Any writing operation to MP will only transfer the lower 7-bit data to MP.

Accumulator ACC

The accumulator (ACC) relates to the ALU operations. It is also mapped to location 05H of the RAM and is capable of operating with immediate data. The data movement between two data memories will pass through the ACC.

Arithmetic and logic unit – ALU

This circuit performs 8-bit arithmetic and logic operations. It provides the following functions:

- Arithmetic operations (ADD, ADC, SUB, SBC, DAA)
- Logic operations (AND, OR, XOR, CPL)
- Rotation (RL, RR, RLC, RRC)
- Increment and Decrement (INC, DEC)
- Branch decision (SZ, SNZ, SIZ, SDZ, etc.)

The ALU saves the results of the data operation and change the status register as well.

Status register – STATUS

The status register (0AH) is of 8 bits wide and consists of a zero flag (Z), a carry flag (C), an auxiliary carry flag (AC), an overflow flag (OV), a power down flag (PD), and a watchdog timeout flag (TO). The register also records the status information and controls the operation sequence.

Except the TO and PD flags, bits in the status register can all be altered by instructions, similar to the case with other registers. Any data written into the status register will not change the TO or PD flags. But the operations related to the status register may lead to different results from those intended. The TO and PD flags can be changed by system power up, Watchdog Timer overflow, executing the HALT instruction, or clearing the Watchdog Timer. The Z, OV, AC, and C flags all reflect the status of the latest operations.

On entering the interrupt sequence or executing the subroutine call, the status register will not be automatically pushed onto the stack. If the contents of the status is important and the subroutine can corrupt the status register, the programmer should take precautions to save it properly.

Interrupt

The four microcontrollers all provide an external interrupt and internal timer/event counter interrupts. The interrupt control register (INTC;0BH) contains interrupt control bits for setting the enable/disable mode and the interrupt request flags.

Once an interrupt subroutine is serviced, the remaining interrupts will all be blocked (by clearing the EMI bit). This scheme may prevent any further interrupt nesting. Other interrupt requests may happen during this interval but only the interrupt request flag will be recorded. If a certain interrupt requires servicing within the service routine, the programmer may set the EMI bit and the corresponding bit of INTC so as to allow interrupt nesting. If the stack is full, the interrupt request will not be acknowledged, even

if the related interrupt is enabled, until the SP is decremented. If immediate servicing is desired, the stack should be prevented from becoming full.

All these interrupts have a wake-up capability. As an interrupt is serviced, a control transfer occurs by pushing the PC onto the stack and then by branching it to subroutines at the specified location(s) in the ROM. Only the contents of the PC can be pushed onto the stack. If the contents of the register and of the status register (STATUS) are altered by the interrupt service program which corrupts the desired control sequence, the programmer should save these contents first.

The external interrupt is triggered by a high to low transition of the INT, and the related interrupt request flag (EIF; bit 4 of INTC) is then set. When the interrupt is enabled, the stack is not full, and the external interrupt is active, a subroutine call to location 04H will occur. The interrupt request flag (EIF) and EMI bits will also be cleared to disable other interrupts.

Of the four microcontrollers, the internal timer/event counter interrupt of the HT48C10/HT48C30 is initialized by setting the timer/

Labels	Bits	Function
C	0	C is set if the operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation; otherwise C is cleared. Also it is affected by a rotate through carry instruction.
AC	1	AC is set if the operation results in a carry out of the low nibbles in addition or no borrow from the high nibble into the low nibble in subtraction; otherwise AC is cleared.
Z	2	Z is set if the result of an arithmetic or logic operation is zero; otherwise Z is cleared.
OV	3	OV is set if the operation results in a carry into the highest-order bit but not a carry out of the highest-order bit, or vice versa; otherwise OV is cleared.
PD	4	PD is cleared by either a system power-up or executing the CLR WDT instruction. PD is set by executing the HALT instruction.
TO	5	TO is cleared by a system power-up or executing the CLR WDT or HALT instruction. TO is set by a WDT time-out.
—	6	Undefined, read as 0
—	7	Undefined, read as 0

Status register

event counter interrupt request flag (TF; bit 5 of INTC), that is caused by a timer overflow. When the interrupt is enabled, and the stack is not full, and the TF bit is set, a subroutine call to location 08H will occur. The related interrupt request flag (TF) will be reset and the EMI bit will be cleared to disable further interrupts.

The internal timer/event counter of the HT48C50/HT48C70, is composed of two interrupts, namely internal timer/event counter 0 interrupt and timer/event counter 1 interrupt. The internal timer/event counter 0 interrupt is initialized by setting the timer/event counter 0 interrupt request flag (T0F; bit 5 of INTC) which is caused by a timer/event counter 0 overflow. After the interrupt is enabled, the stack is not full, and the T0F bit is set, a subroutine call to location 08H will occur. The related interrupt request flag (T0F) will be reset and the EMI bit be cleared to disable further interrupts. On the other hand, the timer/event counter 1 interrupt is operated in the same manner as the timer/event counter 0. The related interrupt control bits ET1I and T1F of the timer/event counter 1 are bit 3 and bit 6 of the INTC, respectively.

During the execution of an interrupt subroutine of the four microcontrollers, other interrupt ac-

knowledgments are all held until the RETI instruction is executed or the EMI bit and the related interrupt control bit are both set to 1 (when the stack is not full). To return from the interrupt subroutine, the RET or RETI instruction may be invoked. The RETI will set the EMI bit in order to enable an interrupt service whereas the RET will not.

Interrupts that occur in an interval between the rising edges of two consecutive T2 pulses are serviced on the latter of the two T2 pulses if the corresponding interrupts are enabled. In case of simultaneous requests, the following table shows the priority that is applied. These can be masked by resetting the EMI bit.

No.	Interrupt Source	Priority	Vector
a	External interrupt	1	04H
b	Timer/event counter 0 overflow	2	08H
*c	Timer/event counter 1 overflow	3	0CH

* Note: c applies only to the HT48C50/ HT48C70

Register	Bit No.	Label	Function
INTC (0BH)	0	EMI	Control the master (global) interrupt (1= enabled; 0= disabled)
	1	EEI	Control the external interrupt (1= enabled; 0= disabled)
	2	ET0I	Control the timer/event counter 0 interrupt (1= enabled; 0= disabled)
	3	ET1I	Control the timer/event counter 1 interrupt (for the HT48C50/HT48C70 only) (1= enabled; 0= disabled)
	4	EIF	External interrupt request flag (1= active; 0= inactive)
	5	T0F	Internal timer/event counter 0 request flag (1= active; 0= inactive)
	6	T1F	Internal timer/event counter 1 request flag (for the HT48C50/HT48C70 only) (1= active; 0= inactive)
	7	—	Unused bit, read as "0"

INTC register

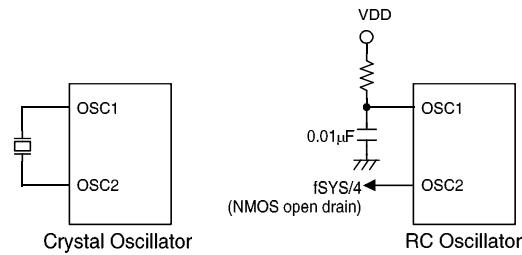
The timer/event counter interrupt request flag (TF), external interrupt request flag (EIF), enable timer/event counter bit (ETI), enable external interrupt bit (EEI), and enable master interrupt bit (EMI) constitute an interrupt control register (INTC) of the HT48C10/HT48C30 which is located at 0BH in the RAM. On the other hand, the timer/event counter 0/1 interrupt request flag (T0F/T1F), external interrupt request flag (EIF), enable timer/event counter 0/1 bit (ET0I/ET1I), enable external interrupt bit (EEI), and enable master interrupt bit (EMI) make up the interrupt control register (INTC) of the HT48C50/HT48C70 which is located at 0BH in the RAM. EMI, EEI, and ETI, of the HT48C10/HT48C30 or EMI, EEI, ET0I, and ET1I of the HT48C50/HT48C70 are all used to control the enable/disable status of interrupts. These bits prevent the requested interrupt from being serviced. Once the interrupt request flags (TF, EIF of the HT48C10/HT48C30 or T0F, T1F, EIF of the HT48C50/HT48C70) are set, they will remain in the INTC register until the interrupts are all serviced or cleared by a software instruction.

It is suggested that a program should not employ the "CALL subroutine" within the interrupt subroutine, since its operation within the interrupt subroutine may damage the original control sequence, and interrupts often occur in an unpredictable manner or it may need immediate servicing for certain applications. Given this, if only one stack is left and enabling the interrupt is not well controlled, the original control sequence may be ruined as a result of operating the CALL subroutine in the interrupt subroutine.

Oscillator configuration

There are 2 oscillator circuits available, namely RC oscillator and crystal oscillator, decided by mask options. Both are designed for system clocks. No matter what type of oscillator is chosen, the signal supports the system clock. The HALT mode stops the system oscillator and ignores any external signals so as to conserve power.

Of the two oscillator types, if an RC oscillator is used, an external resistor between OSC1 and



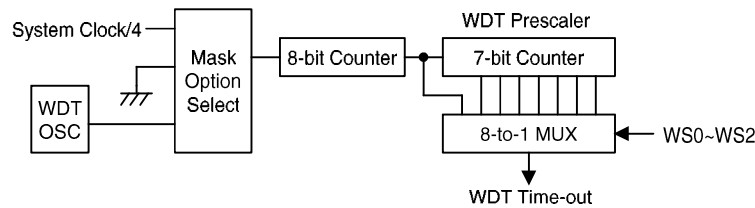
System oscillator

VDD is required and its resistance ranges from 51kΩ to 1MΩ. The system clock, divided by 4, is available on OSC2 (NMOS open drain output), which can be used to synchronize external logic. The RC oscillator provides the most cost effective solution. However, the frequency of the oscillation may vary with VDD, temperature and the chip itself due to process variations. It is, therefore, not suitable for timing sensitive operations where accurate oscillator frequency is desired. On the other hand, if the crystal oscillator is used, a crystal across OSC1 and OSC2 is needed to provide the feedback and phase shift required for the crystal oscillator. No other external components are required. Instead of a crystal, the resonator can also be connected between OSC1 and OSC2 to derive a frequency reference, but two external capacitors in OSC1 and OSC2 are required.

The WDT oscillator is a free running on-chip RC oscillator, and no external components are required. Even if the system enters the power down mode, the system clock is stopped but the WDT oscillator still works with a period of approximately 78 μs. The WDT oscillator can be disabled by mask option to conserve power.

Watchdog timer – WDT

The clock source of the WDT is implemented by a dedicated RC oscillator (WDT oscillator) or an instruction clock (system clock divided by 4), decided by mask options. The WDT is designed to prevent a software malfunction or sequence from jumping to an unknown location with unpredictable results. The WDT can be disabled by mask option. If the WDT is disabled, all the executions related to the WDT may lead to no operation.



Watchdog timer

If the internal WDT oscillator (RC oscillator with a period of 78μs normally) is selected, it is first divided by 256 (8 stages) to derive a nominal time-out period of about 20ms. This time-out period may vary with temperature, VDD, and process variations. By invoking the WDT prescaler, longer time-out periods can be realized. Writing data to WS2, WS1, and WS0 (bit 2,1,0 of the WDTS) can lead to different time-out periods. If the values of WS2, WS1, and WS0 all equal to 1, the division ratio is up to 1:128, and the maximum time-out period is 2.6 seconds.

But if the WDT oscillator is disabled, the WDT clock may still come from the instruction clock and operate in the same manner except that in the HALT state the WDT may stop counting and lose its protecting purpose. In this situation the logic can be restarted by external logic. The high nibble and bit 3 of the WDTS are reserved for user defined flags, and the programmer may use these flags to indicate some specified status.

WS2	WS1	WS0	Division Ratio
0	0	0	1:1
0	0	1	1:2
0	1	0	1:4
0	1	1	1:8
1	0	0	1:16
1	0	1	1:32
1	1	0	1:64
1	1	1	1:128

WDTS Register

If the device operates in a noisy environment, using the on-chip RC oscillator (WDT OSC) is

strongly recommended, since the HALT will terminate the system clock.

The overflow of WDT under normal operation can initialize “chip reset” and set the status bit TO. But in the HALT mode, the overflow will initialize a “warm reset”, and only the PC and SP are reset to zero. To clear the contents of WDT (the WDT prescaler included), three methods can be adopted, i.e., external reset (a low level to $\overline{\text{RES}}$), software instruction(s), and a HALT instruction. The software instruction(s) consists of CLR WDT and the other set — CLR WDT1 and CLR WDT2. Of these two types of instructions, only one type can be active depending on mask option — “CLR WDT times selection option”. If the “CLR WDT” is chosen (i.e., CLRWDT times equal one), any execution of the CLR WDT instruction will clear the WDT. In the case that the “CLR WDT1” and “CLR WDT2” are chosen (i.e., CLRWDT times equal two), these two instructions should be executed to clear the WDT; otherwise, the WDT may reset the chip due to time-out.

Power down operation – HALT

The HALT mode is initialized by the HALT instruction and results in the following.

- The system oscillator turns off but the WDT oscillator keeps running (if the WDT oscillator is selected).
- The contents of the on-chip RAM and registers remain unchanged.
- The WDT and WDT prescaler are cleared and recount (if the WDT clock comes from the WDT oscillator).
- All I/O ports maintain their original status.
- The PD flag is set and the TO flag is cleared.

The system can quit the HALT mode by exter-

nal reset, interrupt, external falling edge signal on port A, or a WDT overflow. An external reset may cause device initialization, and the WDT overflow performs a “warm reset”. Examining the TO and PD flags, the reason for chip reset is determined. The PD flag is cleared by system power-up or executing the CLR WDT instruction, and is set by executing the HALT instruction. The TO flag is set if the WDT time-out occurs, and causes a wake-up that resets the PC and SP only. The others maintain their original status.

The port A wake-up and interrupt methods can be considered as a continuation of normal execution. Each bit in port A can be independently selected to wake up the device by mask option. Awakening from an I/O port stimulus, the program will resume execution of the next instruction. On the other hand, awakening from an interrupt, two sequences may happen. If the related interrupt(s) is disabled or the interrupt(s) is enabled but the stack is full, the program will resume execution at the next instruction. But if the interrupt is enabled and the stack is not full, the regular interrupt response takes place.

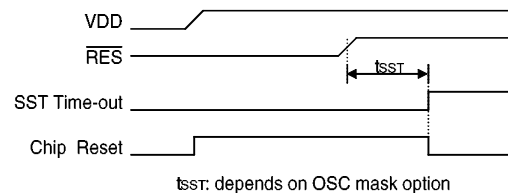
When wake-up event(s) occurs, it takes 1024 t_{sys} (system clock period) to resume normal operation. That is to say, a dummy period is inserted after the wake-up. If the wake-up results from an interrupt acknowledgment, the actual interrupt subroutine execution will be delayed by more than one cycle. But if the wake-up results in the next instruction execution, the instruction will execute immediately after the dummy period is finished. If an interrupt request flag is set to “1” before entering the HALT mode, the make-up function of the related interrupt will be disabled.

To minimize power consumption, all the I/O pins should be carefully managed before entering the HALT status.

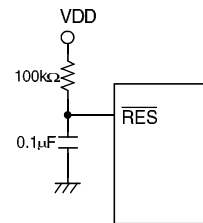
Reset

There are three ways in which reset may occur:

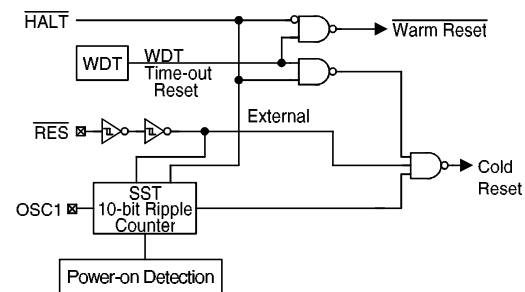
- $\overline{RES}$ is reset during normal operation
- $\overline{RES}$ is reset during HALT
- WDT timeout is reset during normal operation



Reset timing chart



Reset circuit



Reset configuration

WDT time-out during the HALT is different from other chip reset conditions, for it can perform a “warm reset” that resets only PC and SP and leaves the other circuits at their original state. Some registers remain unchanged during any other reset conditions. Most of the registers are reset to the “initial condition” when the reset conditions are met. By examining the PD flag and TO flag, the program distinguishes between different “chip resets”.

TO	PD	RESET Conditions
0	0	$\overline{RES}$ reset during power-up
u	u	$\overline{RES}$ reset during normal operation
0	1	$\overline{RES}$ wake-up HALT

TO	PD	RESET Conditions
1	u	WDT time-out during normal operation
1	1	WDT wake-up HALT

Note: “u” means “unchanged”

To guarantee that the system oscillator is started and stabilized, the SST (System Start-up Timer) provides an extra-delay. The extra-delay delays 1024 system clock pulses when the system powers up or awakes from the HALT state.

When the system power-up occurs, the SST delay is added during the reset period. But when the reset comes from the RES pin, the SST delay is disabled. Any wake-up from HALT will enable the SST delay.

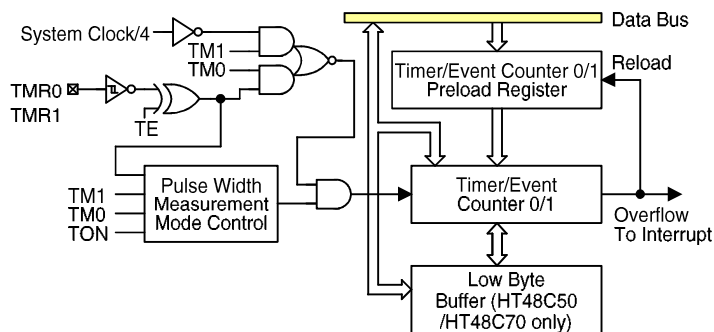
The status of the chip reset of the functional units are as shown.

PC	000H
Interrupt	Disabled
Prescaler	Cleared
WDT	Cleared After a master reset, WDT begins counting.
Timer/event counter (0/1)	Off
Input/output ports	Input mode
SP	Point to the top of the stack

Timer/event counter

There are two timer/event counters implemented in the four microcontrollers. Of the four microcontrollers, the timer/event counter of the HT48C10/HT48C30 contains an 8-bit programmable count-up counter. On the other hand, the timer/event counter of the HT48C50/HT48C70 composes of two counters, namely timer/event counter 0 and timer/event counter 1. The timer/event counter 0 contains a 16-bit programmable counter, and the timer/event counter 1 contains an 8-bit programmable count-up counter of the HT48C50. The timer/event counters 0 and 1 of the HT48C70 both contain a 16-bit programmable count-up counter. The source of the clock of the four microcontrollers may come from an external source or the system clock divided by 4. If the internal instruction clock is applied, only one reference time-base is available. The external clock input, on the other hand, allows the user to count external events, measure time intervals or pulse width, or generate an accurate time base.

Of the HT48C10/HT48C30, there are two registers related to the timer/event counter, i.e., TMR ([0DH]) and TMRC ([0EH]). There are two physical registers mapped to the TMR location. Writing TMR puts the starting value in the timer/event counter preload register while reading TMR gets the contents of the timer/event counter. The TMRC, on the other hand, is a timer/event counter control register.



Timer/event counter 0/1

The states of the special function registers are summarized in the following table:

Register	Reset (power on)	WDT time-out (normal operation)	$\overline{\text{RES}}$ reset (normal operation)	$\overline{\text{RES}}$ reset (HALT)	WDT time-out* (HALT)
TMR1H	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TMR1L	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TMR1C	00-0 1---	00-0 1---	00-0 1---	00-0 1---	uu-u u---
TMR0H	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TMR0L	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TMR0C	00-0 1---	00-0 1---	00-0 1---	00-0 1---	uu-u u---
PC	000H	000H	000H	000H	000H
MP0	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
MP1	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TBLH	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
STATUS	--00 xxxx	--1u uuuu	--uu uuuu	--01 uuuu	--11 uuuu
INTC	-000 0000	-000 0000	-000 0000	-000 0000	-uuu uuuu
WDTS	0000 0111	0000 0111	0000 0111	0000 0111	uuuu uuuu
PA	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PAC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PB	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PBC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PCC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PD	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PDC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PE	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PEC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PF	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PFC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PG	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PGC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu

Note: “*” means “warm reset”

“u” means “unchanged”

“x” means “unknown”

“–” means “undefined”

The bits of the special function registers are denoted as “–” if they are not defined in the microcontrollers.

Of the HT48C50/HT48C70, the timer/event counter is comprised by two counters, i.e., timer/event counter 0 and timer/event counter 1. There are three registers related to the timer/event counter 0, namely TMR0H (0CH), TMR0L (0DH), and TMR0C (0EH). Writing TMR0L only writes the data into a low byte buffer, but writing TMR0H writes the data along with the contents of the low byte buffer into the timer/event counter 0 preload register (16-bit). The timer/event counter 0 preload register is changed by writing the TMR0H operations, and writing TMR0L keeps the timer/event counter 0 preload register unaltered. Also, reading the TMR0H latches the TMR0L into the low byte buffer in order to avoid the false timing problem. Then, reading the TMR0L will return the contents of the low byte buffer. In other words, the low byte of the timer/event counter 0 cannot be read directly. Instead it has to read the TMR0H first in order to make the low byte contents of the timer/event counter 0 latched into the buffer. On the other hand, there are also three registers related to the timer/event counter 1, namely TMR1H (0FH), TMR1L (10H), and TMR1C (11H). The timer/event counter 1 operates in the same manner as the timer/event counter 0.

The TMR0C is a timer/event counter 0 control register defining the timer/event counter 0 options. The timer/event counter 1 has the same

options as the timer/event counter 0 and is defined by TMR1C.

The timer/event counter control registers of the four microcontrollers are all used to define the operation mode, counting enable or disable, and active edge.

The TM0 and TM1 bits define the operation mode. The event count mode is used to count external events, which means that the clock source comes from an external pin TMR of the HT48C10/HT48C30 or TMR0/TMR1 of the HT48C50/HT48C70. The timer mode functions as a normal timer with the clock source coming from the instruction clock. The pulse width measurement mode can be used to count the high or low level duration of the external signal TMR of the HT48C10/HT48C30 or TMR0/TMR1 of the HT48C50/HT48C70. The counting is based on the instruction clock.

In the event count or timer mode, once the timer/event counter starts counting, it will count from the current contents in the timer/event counter to FFH of the HT48C10/HT48C30/HT48C50 (TMR1) or to FFFFH of the HT48C50 (TMR0)/HT48C70. If an overflow occurs, the counter is reloaded from the timer/event counter preload register and generates the corresponding interrupt request flag TF (bit 5 of INTC) of the HT48C10/HT48C30 or T0F/T1F (bit 5/6 of INTC) of the HT48C50/HT48C70 at the same time.

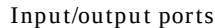
Label	Bits	Function
—	0~2	Unused bits, read as “0”
TE	3	To define TMR0/TMR1 active edge of the timer/event counter (0= active on low to high; 1= active on high to low)
TON	4	To enable/disable timer counting (0= disabled; 1= enabled)
—	5	Unused bits, read as “0”
TM0 TM1	6 7	To define the operating mode 01= Event count mode (external clock) 10= Timer mode (internal clock) 11= Pulse width measurement mode 00= Unused

TMR0C/TMR1C register

To enable the counting operation, the timer ON bit (TON; bit 4 of TMRC of the HT48C10/HT48C30 or bit 4 of TMR0C/TMR1C of the HT48C50/HT48C70) should be set to 1. In the pulse width measurement mode, the TON will be cleared automatically after the measurement cycle is complete. But in the other two modes the TON can only be reset by instructions. The overflow of the timer/event counter is one of the wake-up sources. No matter what the operation mode is, writing a 0 to ETI of the

After the timer/event counter (reading TMR of the HT48C10/HT48C30 or TMR0H, TMR1H of the HT48C50/HT48C70) is read, the clock is blocked to avoid errors. As this may result in a counting error, blocking of the clock should be taken into account by the programmer.

There are various numbers of bidirectional input/output lines in the four microcontrollers. The HT48C10 includes 18 bidirectional input/output lines, labeled from PA to PC, which are mapped to the [12H], [14H], or [16H] of the RAM, respectively. The HT48C30 contains 22 bidirectional input/output lines, labeled from PA to PC, which are mapped to [12H], [14H], or [16H], respectively. The HT48C50 consists of 32



bidirectional input/output lines, labeled from PA to PD, which are mapped to the [12H], [14H], [16H], or [18H], respectively. Finally, the HT48C70 contains 56 bidirectional input/output lines, labeled from PA to PG, which are mapped to the RAM of [12H], [14H], [16H], [18H], [1AH], [1CH], and [1EH], respectively. Of the four microcontrollers, all of these I/O ports can be used for input and output operations. For the input operation, these ports are non-latching, i.e., the inputs should be ready at the T2 rising edge of the instruction MOV A,[m] (m=12H, 14H, 16H, 18H, 1AH, 1CH, or 1EH). For the output operation, all data are latched and remain unchanged until the output latch is rewritten.

Each I/O line has its own control register (PAC, PBC, PCC, PDC, PEC, PFC, PGC (the first three registers PAC, PBC, PCC are all used by the four microcontrollers; the register PDC is extra-used by the HT48C50; all the seven registers are applied in the HT48C70) to control the input/output configuration. With this control register, CMOS output or schmitt trigger input with or without pull-high resistor (by mask option) structures can be reconfigured dynamically (i.e., on-the-fly) under software control. To function as an input, the corresponding latch of the control register must be written with a "1". The pull-high resistance shows itself automatically if the pull-high option is selected. The input source(s) also depends on the control register. If the value of the control register bit is "1", the input will read the pad state. But if the value of the control register bit is "0", the contents of the latches will be moved to the internal bus. The latter is possible in "read-modify-write" instruction. For the output function, CMOS is the only configuration. These control registers are mapped to locations 13H, 15H, 17H, 19H, 1BH, 1DH and 1FH (the first three locations 13H, 15H, 17H exist in the four microcontrollers; the location 19H is used for the HT48C50; all the 7 locations are applied in the HT48C70).

After a chip reset, these input/output lines stay at the high level or floating (by mask option). Each bit of these input/output latches can be set or cleared by the SET [m].i or CLR [m].i (m=12H,

14H, 16H, 18H, 1AH, 1CH or 1EH (the first three options, namely 12H, 14H, and 16H, exist in the four microcontrollers; the HT48C50 is provided with an extra option of 18H; these seven options all exist in the HT48C70) instruction.

Some instructions first input data and then follow the output operations. For example, the SET [m].i, CLR [m].i, CPL [m] and CPLA [m] instructions read the entire port states into the CPU, execute the defined operations (bit-operation), and then write the results back to the latches or the accumulator.

Each line of port A has the capability to wake-up the device.

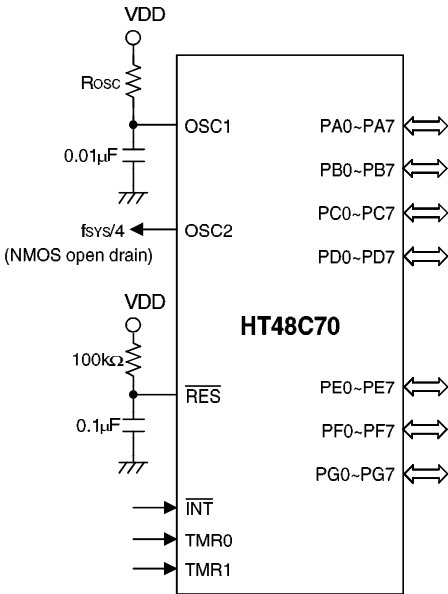
Mask option

The following table illustrates the five kinds of mask option provided. All these options have to be defined to ensure proper system functioning.

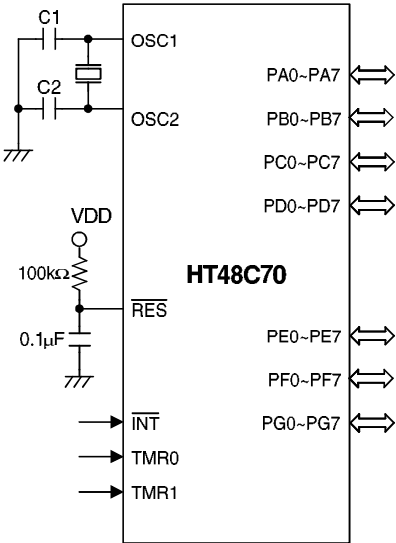
No.	Mask Option
1	OSC type selection. This option is to decide if an RC or Crystal oscillator is chosen as system clock. If the Crystal oscillator is selected, the XST (Crystal Start-up Timer) default is activated; otherwise the XST is disabled.
2	WDT source selection. There are three types of selection: on-chip RC oscillator, instruction clock or disable the WDT.
3	CLRWDT times selection. This option defines the way of clearing the WDT by instruction. "Once" means that the CLR WDT instruction can clear the WDT. "Twice" means only if both of the CLR WDT1 and CLR WDT2 instructions have been executed, the WDT can be cleared.
4	Wake-up selection. This option defines the activity of the wake-up function. External I/O pins (PA only) all have the capability to wake-up the chip from a HALT.

Application Circuits of HT48C70

RC oscillator for multiple I/O applications



Crystal oscillator or ceramic resonator for multiple I/O applications



f _{sys} (kHz)	C1	C2	Crystal	Ceramic resonator
8000	0	0	OK	OK
6000	0	0	OK	OK
4000	0	0	OK	OK
3580	0	0	OK	OK
2000	0	0	OK	OK
1000	0	0	OK	—
640	300pF	300pF	—	OK
480	300pF	300pF	—	OK
455	300pF	300pF	—	OK
400	300pF	300pF	—	OK

Instruction Set Summary

Mnemonic	Description	Flag Affected	Instruction Cycle
Arithmetic			
ADD A,[m]	Add data memory to ACC	Z,C,AC,OV	1
ADDM A,[m]	Add ACC to data memory	Z,C,AC,OV	1 ⁽¹⁾
ADD A,x	Add immediate data to ACC	Z,C,AC,OV	1
ADC A,[m]	Add data memory to ACC with carry	Z,C,AC,OV	1
ADCM A,[m]	Add ACC to register with carry	Z,C,AC,OV	1 ⁽¹⁾
SUB A,x	Subtract immediate data from ACC	Z,C,AC,OV	1
SUB A,[m]	Subtract data memory from ACC	Z,C,AC,OV	1
SUBM A,[m]	Subtract data memory from ACC with result in data memory	Z,C,AC,OV	1 ⁽¹⁾
SBC A,[m]	Subtract data memory from ACC with carry	Z,C,AC,OV	1
SBCM A,[m]	Subtract data memory from ACC with carry with result in data memory	Z,C,AC,OV	1 ⁽¹⁾
DAA [m]	Decimal adjust ACC for addition with result in data memory	C	1 ⁽¹⁾
Logic Operation			
AND A,[m]	AND data memory to ACC	Z	1
OR A,[m]	OR data memory to ACC	Z	1
XOR A,[m]	Exclusive-OR data memory to ACC	Z	1
ANDM A,[m]	AND ACC to data memory	Z	1 ⁽¹⁾
ORM A,[m]	OR ACC to data memory	Z	1 ⁽¹⁾
XORM A,[m]	Exclusive-OR ACC to data memory	Z	1 ⁽¹⁾
AND A,x	AND immediate data to ACC	Z	1
OR A,x	OR immediate data to ACC	Z	1
XOR A,x	Exclusive-OR immediate data to ACC	Z	1
CPL [m]	Complement data memory	Z	1 ⁽¹⁾
CPLA [m]	Complement data memory with result in ACC	Z	1
Increment & Decrement			
INCA [m]	Increment data memory with result in ACC	Z	1
INC [m]	Increment data memory	Z	1 ⁽¹⁾
DECA [m]	Decrement data memory with result in ACC	Z	1
DEC [m]	Decrement data memory	Z	1 ⁽¹⁾

Mnemonic	Description	Flag Affected	Instruction Cycle
Rotate			
RRA [m]	Rotate data memory right with result in ACC	None	1
RR [m]	Rotate data memory right	None	1 ⁽¹⁾
RRCA [m]	Rotate data memory right through carry with result in ACC	C	1
RRC [m]	Rotate data memory right through carry	C	1 ⁽¹⁾
RLA [m]	Rotate data memory left with result in ACC	None	1
RL [m]	Rotate data memory left	None	1 ⁽¹⁾
RLCA [m]	Rotate data memory left through carry with result in ACC	C	1
RLC [m]	Rotate data memory left through carry	C	1 ⁽¹⁾
Data Move			
MOV A,[m]	Move data memory to ACC	None	1
MOV [m],A	Move ACC to data memory	None	1 ⁽¹⁾
MOV A,x	Move immediate data to ACC	None	1
Bit Operation			
CLR [m].i	Clear bit of data memory	None	1 ⁽¹⁾
SET [m].i	Set bit of data memory	None	1 ⁽¹⁾
Branch			
JMP addr	Jump unconditionally	None	2
SZ [m]	Skip if data memory is zero	None	1 ⁽²⁾
SZA [m]	Skip if data memory is zero with data movement to ACC	None	1 ⁽²⁾
SZ [m].i	Skip if bit i of data memory is zero	None	1 ⁽²⁾
SNZ [m].i	Skip if bit i of data memory is not zero	None	1 ⁽²⁾
SIZ [m]	Skip if increment data memory is zero	None	1 ⁽³⁾
SDZ [m]	Skip if decrement data memory is zero	None	1 ⁽³⁾
SIZA [m]	Skip if increment data memory is zero with result in ACC	None	1 ⁽²⁾
SDZA [m]	Skip if decrement data memory is zero with result in ACC	None	1 ⁽²⁾
CALL addr	Subroutine call	None	2
RET	Return from subroutine	None	2
RET A,x	Return from subroutine and load immediate data to ACC	None	2
RETI	Return from interrupt	None	2
Table Read			
TABRDC [m]	Read ROM code (current page) to data memory and TBLH	None	2 ⁽¹⁾
TABRDL [m]	Read ROM code (last page) to data memory and TBLH	None	2 ⁽¹⁾

Mnemonic	Description	Flag Affected	Instruction Cycle
Miscellaneous			
NOP	No operation	None	1
CLR [m]	Clear data memory	None	1 ⁽¹⁾
SET [m]	Set data memory	None	1 ⁽¹⁾
CLR WDT	Clear Watchdog timer	TO,PD	1
CLR WDT1	Pre-clear Watchdog timer	TO*,PD*	1
CLR WDT2	Pre-clear Watchdog timer	TO*,PD*	1
SWAP [m]	Swap nibbles of data memory	None	1 ⁽¹⁾
SWAPA [m]	Swap nibbles of data memory with result in ACC	None	1
HALT	Enter power down mode	TO,PD	1

Notes: x: 8-bit immediate data

m: 7-bit data memory address for HT48C10/HT48C30

m: 8-bit data memory address for HT48C50/HT48C70

A: Accumulator

i: 0~7 number of bits

A: Accumulator

i: 0~7 number of bits

addr: Program memory address

√: Flag(s) is affected

—: Flag(s) is not affected

*: Flag(s) may be affected by the execution status

⁽¹⁾: If a loading to PCL register occurs, the execution cycle of the instructions will be delayed one more cycle (4 system clocks).

⁽²⁾: If a skip to next instruction occurs, the execution cycle of instructions will be delayed one more cycle (4 system clocks). Otherwise the original execution cycles remain unchanged.

⁽³⁾: ⁽¹⁾ or ⁽²⁾

Instruction Definition

ADC A,[m]

Add data memory and carry to the accumulator

Description

The contents of the specified data memory, accumulator and the carry flag are added simultaneously, leaving the result in the accumulator.

Operation

$ACC \leftarrow ACC + [m] + C$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	√	√	√	√

ADCM A,[m]

Add the accumulator and carry to data memory

Description

The contents of the specified data memory, accumulator and the carry flag are added simultaneously, leaving the result in the specified data memory.

Operation

$[m] \leftarrow ACC + [m] + C$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	√	√	√	√

ADD A,[m]

Add data memory to the accumulator

Description

The contents of the specified data memory and the accumulator are added. The result is stored in the accumulator.

Operation

$ACC \leftarrow ACC + [m]$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	√	√	√	√

ADD A,x

Add immediate data to the accumulator

Description

The contents of the accumulator and the specified data are added, leaving the result in the accumulator.

Operation

$ACC \leftarrow ACC + x$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	√	√	√	√

ADDM A,[m] Add the accumulator to the data memory

Description The contents of the specified data memory and the accumulator are added. The result is stored in the data memory.

Operation $[m] \leftarrow ACC + [m]$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	√	√	√	√

AND A,[m] Logical AND accumulator with data memory

Description Data in the accumulator and the specified data memory perform a bitwise logical_AND operation. The result is stored in the accumulator.

Operation $ACC \leftarrow ACC \text{ “AND” } [m]$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	√	–	–

AND A,x Logical AND immediate data to the accumulator

Description Data in the accumulator and the specified data perform a bitwise logical_AND operation. The result is stored in the accumulator.

Operation $ACC \leftarrow ACC \text{ “AND” } x$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	√	–	–

ANDM A,[m] Logical AND data memory with the accumulator

Description Data in the specified data memory and the accumulator perform a bitwise logical_AND operation. The result is stored in the data memory.

Operation $[m] \leftarrow ACC \text{ “AND” } [m]$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	√	–	–

CALL addr Subroutine call

Description The instruction unconditionally calls a subroutine located at the indicated address. The program counter increments once to obtain the address of the next instruction, and pushes this onto the stack. The indicated address is then loaded. Program execution continues with the instruction at this address.

Operation $\text{Stack} \leftarrow \text{PC}+1$
 $\text{PC} \leftarrow \text{addr}$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

CLR [m] Clear data memory

Description The contents of the specified data memory are cleared to zero.

Operation $[\text{m}] \leftarrow 00\text{H}$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

CLR [m].i Clear bit of data memory

Description The bit i of the specified data memory is cleared to zero.

Operation $[\text{m}].i \leftarrow 0$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

CLR WDT Clear watchdog timer

Description The WDT and the WDT Prescaler are cleared (re-counting from zero). The power down bit (PD) and time-out bit (TO) are cleared.

Operation $\text{WDT and WDT Prescaler} \leftarrow 00\text{H}$
 $\text{PD and TO} \leftarrow 0$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	0	0	–	–	–	–

CLR WDT1

Preclear watchdog timer

Description

The TD, PD flags, WDT and the WDT Prescaler has cleared (re-counting from zero), if the other preclear WDT instruction has been executed. Only execution of this instruction without the other preclear instruction sets the indicated flag which implies that this instruction has been executed and the TO and PD flags remain unchanged.

Operation

WDT and WDT Prescaler $\leftarrow$ 00H*
PD and TO $\leftarrow$ 0*

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
—	—	0*	0*	—	—	—	—

CLR WDT2

Preclear watchdog timer

Description

The TO, PD flags, WDT and the WDT Prescaler are cleared (re-counting from zero), if the other preclear WDT instruction has been executed. Only execution of this instruction without the other preclear instruction sets the indicated flag which implies that this instruction has been executed and the TO and PD flags remain unchanged.

Operation

WDT and WDT Prescaler $\leftarrow$ 00H*
PD and TO $\leftarrow$ 0*

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
—	—	0*	0*	—	—	—	—

CPL [m]

Complement data memory

Description

Each bit of the specified data memory is logically complemented (1's complement). Bits which previously contained a one are changed to zero and vice-versa.

Operation

$[m] \leftarrow \overline{[m]}$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
—	—	—	—	—	√	—	—

CPLA [m] Complement data memory and place result in the accumulator

Description Each bit of the specified data memory is logically complemented (1's complement). Bits which previously contained a one are changed to zero and vice-versa. The complemented result is stored in the accumulator and the contents of the data memory remain unchanged.

Operation $ACC \leftarrow \overline{[m]}$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
—	—	—	—	—	√	—	—

DAA [m] Decimal-Adjust accumulator for addition

Description The accumulator value is adjusted to the BCD (Binary Code Decimal) code. The accumulator is divided into two nibbles. Each nibble is adjusted to the BCD code and an internal carry (AC1) will be done if the low nibble of the accumulator is greater than 9. The BCD adjustment is done by adding 6 to the original value if the original value is greater than 9 or a carry (AC or C) is set; otherwise the original value remains unchanged. The result is stored in the data memory and only the carry flag (C) may be affected.

Operation If $ACC.3 \sim ACC.0 > 9$ or $AC=1$
then $[m].3 \sim [m].0 \leftarrow (ACC.3 \sim ACC.0) + 6, AC1 = \overline{AC}$
else $[m].3 \sim [m].0 \leftarrow (ACC.3 \sim ACC.0), AC1 = 0$
and
If $ACC.7 \sim ACC.4 + AC1 > 9$ or $C=1$
then $[m].7 \sim [m].4 \leftarrow ACC.7 \sim ACC.4 + 6 + AC1, C=1$
else $[m].7 \sim [m].4 \leftarrow ACC.7 \sim ACC.4 + AC1, C=C$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
—	—	—	—	—	—	—	√

DEC [m] Decrement data memory

Description Data in the specified data memory is decremented by one.

Operation $[m] \leftarrow [m] - 1$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
—	—	—	—	—	√	—	—

DECA [m]	Decrement data memory and place result in the accumulator
Description	Data in the specified data memory is decremented by one, leaving the result in the accumulator. The contents of the data memory remain unchanged.
Operation	$ACC \leftarrow [m]-1$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	√	–	–

HALT	Enter power down mode
Description	This instruction stops program execution and turns off the system clock. The contents of the RAM and registers are retained. The WDT and prescaler are cleared. The power down bit (PD) is set and the WDT time-out bit (TO) is cleared.
Operation	$PC \leftarrow PC+1$ $PD \leftarrow 1$ $TO \leftarrow 0$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	0	1	–	–	–	–

INC [m]	Increment data memory
Description	Data in the specified data memory is incremented by one.
Operation	$[m] \leftarrow [m]+1$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	√	–	–

INCA [m]	Increment data memory and place result in the accumulator
Description	Data in the specified data memory is incremented by one, leaving the result in the accumulator. The contents of the data memory remain unchanged.
Operation	$ACC \leftarrow [m]+1$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	√	–	–

JMP addr	Directly jump
Description	The contents of the program counter are replaced with the directly-specified address unconditionally, and control is passed to this destination.
Operation	$PC \leftarrow \text{addr}$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

MOV A,[m]	Move data memory to the accumulator
Description	The contents of the specified data memory are copied to the accumulator.
Operation	$ACC \leftarrow [m]$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

MOV A,x	Move immediate data to the accumulator
Description	The 8-bit data specified by the code is loaded into the accumulator.
Operation	$ACC \leftarrow x$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

MOV [m],A	Move the accumulator to data memory
Description	The contents of the accumulator are copied to the specified data memory (one of the data memories).
Operation	$[m] \leftarrow ACC$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

NOP	No operation
Description	No operation is performed. Execution continues with the next instruction.
Operation	$PC \leftarrow PC+1$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

OR A,[m]

Logical OR accumulator with data memory

Description

Data in the accumulator and the specified data memory (one of the data memories) perform a bitwise logical_OR operation. The result is stored in the accumulator.

Operation

$ACC \leftarrow ACC \text{ "OR" } [m]$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	√	–	–

OR A,x

Logical OR immediate data to the accumulator

Description

Data in the accumulator and the specified data perform a bitwise logical_OR operation. The result is stored in the accumulator.

Operation

$ACC \leftarrow ACC \text{ "OR" } x$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	√	–	–

ORM A,[m]

Logical OR data memory with the accumulator

Description

Data in the data memory (one of the data memories) and the accumulator perform a bitwise logical_OR operation. The result is stored in the data memory.

Operation

$[m] \leftarrow ACC \text{ "OR" } [m]$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	√	–	–

RET

Return from subroutine

Description

The program counter is restored from the stack. This is a two-cycle instruction.

Operation

$PC \leftarrow \text{Stack}$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

RET A,x Return and place immediate data in the accumulator

Description The program counter is restored from the stack and the accumulator loaded with the specified 8-bit immediate data.

Operation $PC \leftarrow \text{Stack}$
 $ACC \leftarrow x$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

RETI Return from interrupt

Description The program counter is restored from the stack, and interrupts are enabled by setting the EMI bit. EMI is the enable master (global) interrupt bit (bit 0; register INTC).

Operation $PC \leftarrow \text{Stack}$
 $EMI \leftarrow 1$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

RL [m] Rotate data memory left

Description The contents of the specified data memory are rotated one bit left with bit 7 rotated into bit 0.

Operation $[m].(i+1) \leftarrow [m].i$; $[m].i$:bit i of the data memory (i=0-6)
 $[m].0 \leftarrow [m].7$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

RLA [m] Rotate data memory left and place result in the accumulator

Description Data in the specified data memory is rotated one bit left with bit 7 rotated into bit 0, leaving the rotated result in the accumulator. The contents of the data memory remain unchanged.

Operation $ACC.(i+1) \leftarrow [m].i$; $[m].i$:bit i of the data memory (i=0-6)
 $ACC.0 \leftarrow [m].7$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

RLC [m]	Rotate data memory left through carry
Description	The contents of the specified data memory and the carry flag are rotated one bit left. Bit 7 replaces the carry bit; the original carry flag is rotated into the bit 0 position.
Operation	$[m].(i+1) \leftarrow [m].i$; $[m].i$:bit i of the data memory (i=0-6) $[m].0 \leftarrow C$ $C \leftarrow [m].7$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	√

RLCA [m]	Rotate left through carry and place result in the accumulator
Description	Data in the specified data memory and the carry flag are rotated one bit left. Bit 7 replaces the carry bit and the original carry flag is rotated into bit 0 position. The rotated result is stored in the accumulator but the contents of the data memory remain unchanged.
Operation	$ACC.(i+1) \leftarrow [m].i$; $[m].i$:bit i of the data memory (i=0-6) $ACC.0 \leftarrow C$ $C \leftarrow [m].7$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	√

RR [m]	Rotate data memory right
Description	The contents of the specified data memory are rotated one bit right with bit 0 rotated to bit 7.
Operation	$[m].i \leftarrow [m].(i+1)$; $[m].i$:bit i of the data memory (i=0-6) $[m].7 \leftarrow [m].0$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

RRA [m]	Rotate right-place result in the accumulator
Description	Data in the specified data memory is rotated one bit right with bit 0 rotated into bit 7, leaving the rotated result in the accumulator. The contents of the data memory remain unchanged.
Operation	$ACC.i \leftarrow [m].(i+1)$; $[m].i$:bit i of the data memory (i=0-6) $ACC.7 \leftarrow [m].0$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

RRC [m]	Rotate data memory right through carry
Description	The contents of the specified data memory and the carry flag are together rotated one bit right. Bit 0 replaces the carry bit; the original carry flag is rotated into the bit 7 position.
Operation	$[m].i \leftarrow [m].(i+1)$; $[m].i$:bit i of the data memory (i=0-6) $[m].7 \leftarrow C$ $C \leftarrow [m].0$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	√

RRCA [m]	Rotate right through carry-place result in the accumulator
Description	Data of the specified data memory and the carry flag are rotated one bit right. Bit 0 replaces the carry bit and the original carry flag is rotated into the bit 7 position. The rotated result is stored in the accumulator. The contents of the data memory remain unchanged.
Operation	$ACC.i \leftarrow [m].(i+1)$; $[m].i$:bit i of the data memory (i=0-6) $ACC.7 \leftarrow C$ $C \leftarrow [m].0$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	√

SBC A,[m]	Subtract data memory and carry from the accumulator
Description	The contents of the specified data memory and the complement of the carry flag are subtracted from the accumulator, leaving the result in the accumulator.
Operation	$ACC \leftarrow ACC + [\overline{m}] + C$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	√	√	√	√

SBCM A,[m]	Subtract data memory and carry from the accumulator
Description	The contents of the specified data memory and the complement of the carry flag are subtracted from the accumulator, leaving the result in the data memory.
Operation	$[m] \leftarrow ACC + [\overline{m}] + C$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	√	√	√	√

SDZ [m]	Skip if decrement data memory is zero
Description	The contents of the specified data memory are decremented by one. If the result is zero, the next instruction is skipped. If the result is zero, the following instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruction (two cycles). Otherwise proceed with the next instruction (one cycle).
Operation	Skip if $([m]-1)=0$, $[m] \leftarrow ([m]-1)$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

SDZA [m]	Decrement data memory and place result in ACC, skip if zero
Description	The contents of the specified data memory are decremented by one. If the result is zero, the next instruction is skipped. The result is stored in the accumulator but the data memory remains unchanged. If the result is zero, the following instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruction (two cycles). Otherwise proceed with the next instruction (one cycle).
Operation	Skip if $([m]-1)=0$, $ACC \leftarrow ([m]-1)$
Affected flag(s)	

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

SET [m]

Set data memory

Description

Each bit of the specified data memory is set to one.

Operation

 $[m] \leftarrow FFH$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

SET [m].i

Set bit of data memory

Description

Bit “i” of the specified data memory is set to one.

Operation

 $[m].i \leftarrow 1$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

SIZ [m]

Skip if increment data memory is zero

Description

The contents of the specified data memory are incremented by one. If the result is zero, the following instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruction (two cycles). Otherwise proceed with the next instruction (one cycle).

Operation

Skip if $([m]+1)=0$, $[m] \leftarrow ([m]+1)$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

SIZA [m]

Increment data memory and place result in ACC, skip if zero

Description

The contents of the specified data memory are incremented by one. If the result is zero, the next instruction is skipped and the result is stored in the accumulator. The data memory remains unchanged. If the result is zero, the following instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruction (two cycles). Otherwise proceed with the next instruction (one cycle).

Operation

Skip if $([m]+1)=0$, $ACC \leftarrow ([m]+1)$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

SNZ [m].i

Description

Skip if bit “i” of the data memory is not zero

If bit “i” of the specified data memory is not zero, the next instruction is skipped. If bit “i” of the data memory is not zero, the following instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruction (two cycles). Otherwise proceed with the next instruction (one cycle).

Operation

Skip if [m].i≠0

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

SUB A,[m]

Description

Subtract data memory from the accumulator

The specified data memory is subtracted from the contents of the accumulator, leaving the result in the accumulator.

Operation

 $ACC \leftarrow ACC + \overline{[m]} + 1$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	√	√	√	√

SUBM A,[m]

Description

Subtract data memory from the accumulator

The specified data memory is subtracted from the contents of the accumulator, leaving the result in the data memory.

Operation

 $[m] \leftarrow ACC + \overline{[m]} + 1$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	√	√	√	√

SUB A,x

Description

Subtract immediate data from the accumulator

The immediate data specified by the code is subtracted from the contents of the accumulator, leaving the result in the accumulator.

Operation

 $ACC \leftarrow ACC + \overline{x} + 1$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	√	√	√	√

SWAP [m]

Swap nibbles within the data memory

Description

The low-order and high-order nibbles of the specified data memory (one of the data memories) are interchanged.

Operation

 $[m].3 \sim [m].0 \leftrightarrow [m].7 \sim [m].4$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

SWAPA [m]

Swap data memory-place result in the accumulator

Description

The low-order and high-order nibbles of the specified data memory are interchanged, writing the result to the accumulator. The contents of the data memory remain unchanged.

Operation

 $ACC.3 \sim ACC.0 \leftarrow [m].7 \sim [m].4$
 $ACC.7 \sim ACC.4 \leftarrow [m].3 \sim [m].0$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

SZ [m]

Skip if data memory is zero

Description

If the contents of the specified data memory are zero, the following instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruction (two cycles). Otherwise proceed with the next instruction (one cycle).

Operation

 Skip if $[m]=0$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

SZA [m]

Move data memory to ACC, skip if zero

Description

The contents of the specified data memory are copied to the accumulator. If the contents is zero, the following instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruction (two cycles). Otherwise proceed with the next instruction (one cycle).

Operation

 Skip if $[m]=0$, $ACC \leftarrow [m]$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

SZ [m].i Skip if bit “i” of the data memory is zero

Description If bit “i” of the specified data memory is zero, the following instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruction (two cycles). Otherwise proceed with the next instruction (one cycle).

Operation Skip if [m].i=0

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

TABRDC [m] Move the ROM code (current page) to TBLH and data memory

Description The low byte of ROM code (current page) addressed by the table pointer (TBLP) is moved to the specified data memory and the high byte transferred to TBLH directly.

Operation [m] ← ROM code (low byte)
TBLH ← ROM code (high byte)

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

TABRDL [m] Move the ROM code (last page) to TBLH and data memory

Description The low byte of ROM code (last page) addressed by the table pointer (TBLP) is moved to the data memory and the high byte transferred to TBLH directly.

Operation [m] ← ROM code (low byte)
TBLH ← ROM code (high byte)

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	–	–	–

XOR A,[m] Logical XOR accumulator with data memory

Description Data in the accumulator and the indicated data memory perform a bitwise logical Exclusive_OR operation and the result is stored in the accumulator.

Operation ACC ← ACC “XOR” [m]

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
–	–	–	–	–	√	–	–

XORM A,[m]

Logical XOR data memory with the accumulator

Description

Data in the indicated data memory and the accumulator perform a bitwise logical Exclusive_OR operation. The result is stored in the data memory. The zero flag is affected.

Operation

$[m] \leftarrow \text{ACC "XOR"} [m]$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
—	—	—	—	—	√	—	—

XOR A,x

Logical XOR immediate data to the accumulator

Description

Data in the the accumulator and the specified data perform a bitwise logical Exclusive_OR operation. The result is stored in the accumulator. The zero flag is affected.

Operation

$\text{ACC} \leftarrow \text{ACC "XOR"} x$

Affected flag(s)

TC2	TC1	TO	PD	OV	Z	AC	C
—	—	—	—	—	√	—	—

Characteristic Curves

Figure A: Typical RC oscillator frequency vs. temperature

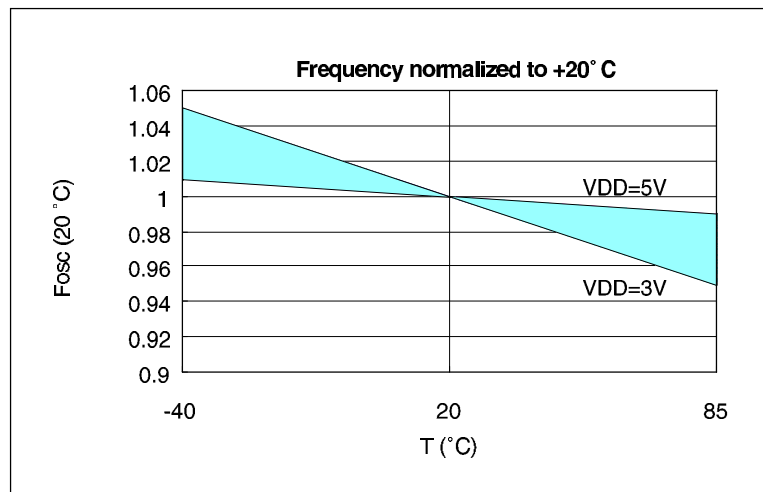


Figure B: Typical RC oscillator frequency vs. V_{DD}

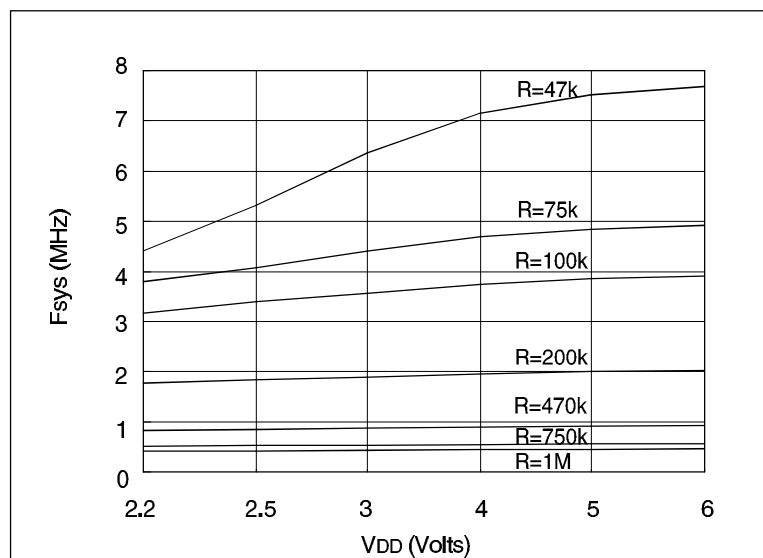


Figure C: I_{OH} vs. V_{OH} , $V_{DD}=3V$

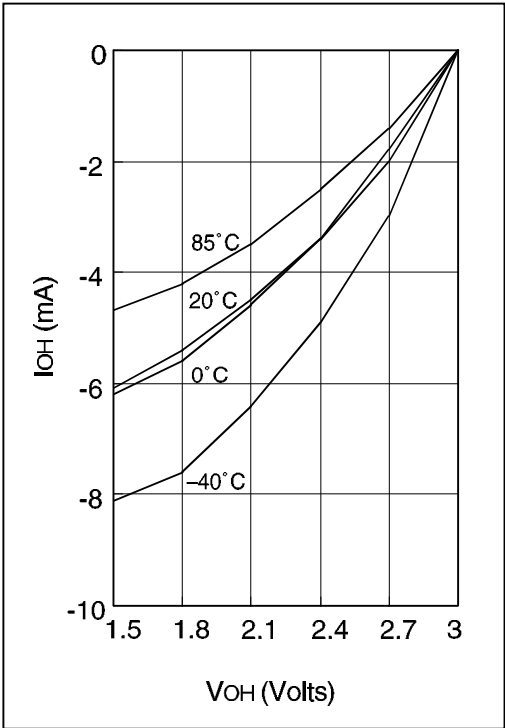


Figure D: I_{OH} vs. V_{OH} , $V_{DD}=5V$

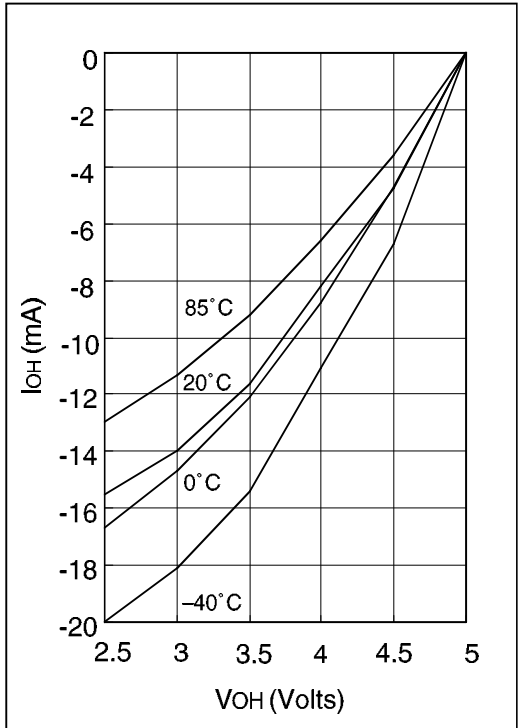


Figure E: I_{OL} vs. V_{OL} , $V_{DD}=3V$

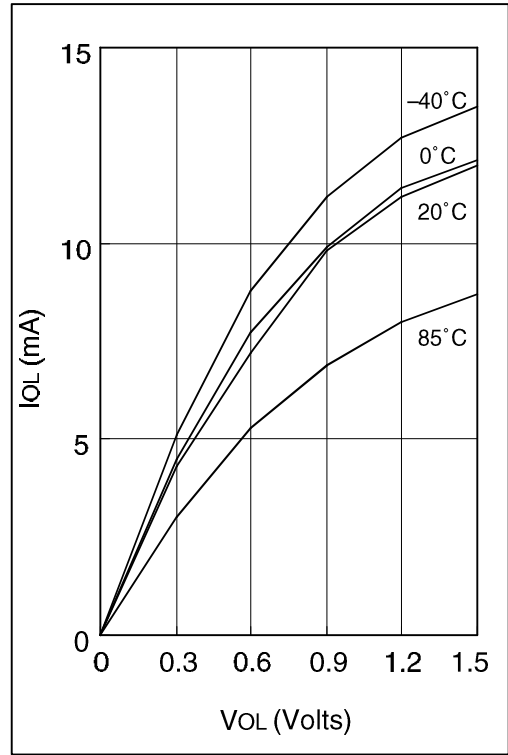


Figure F: I_{OL} vs. V_{OL} , $V_{DD}=5V$

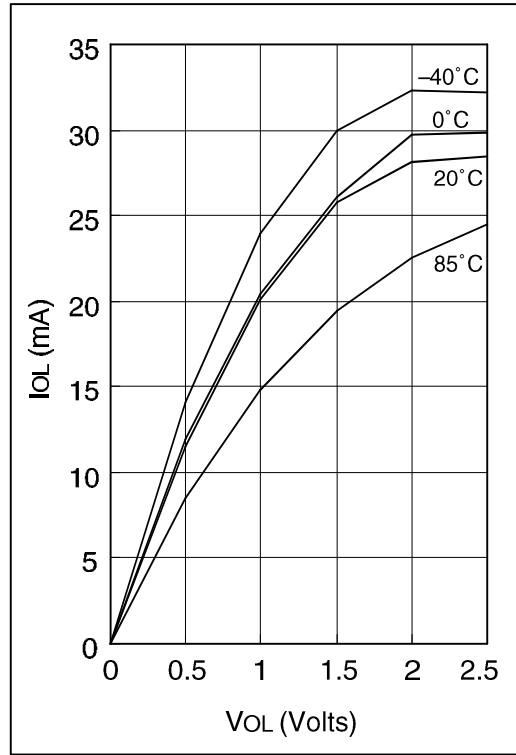


Figure G: V_{DD} vs. R_{PH} in Max.

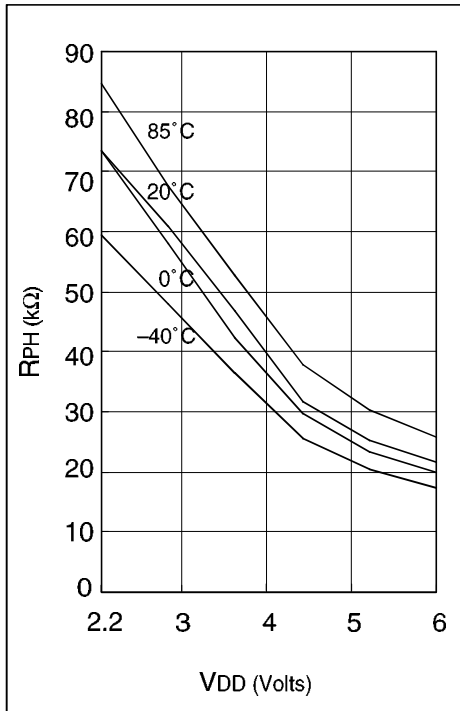
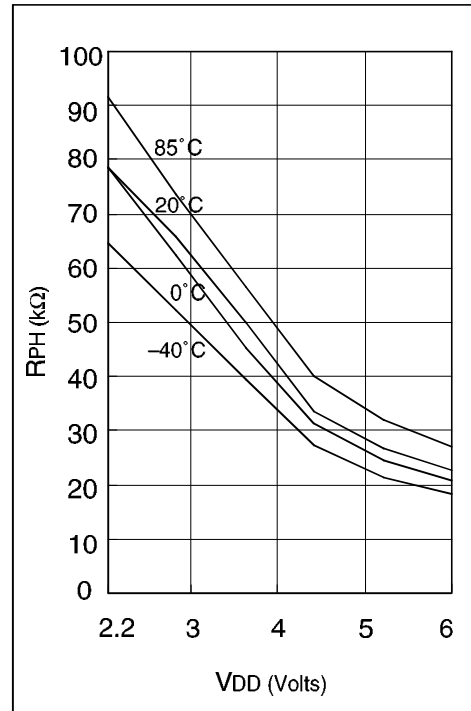


Figure H: V_{DD} vs. R_{PH} in Min.



***Note:**

$$R_{PH} = \frac{V_{DD}}{I_{RPH}}$$

I_{RPH} : Source current while forcing through the I/O port (input mode & pull-high option) to VSS.

Figure I: V_{IH} , V_{IL} vs. V_{DD} in -40°C to $+85^{\circ}\text{C}$

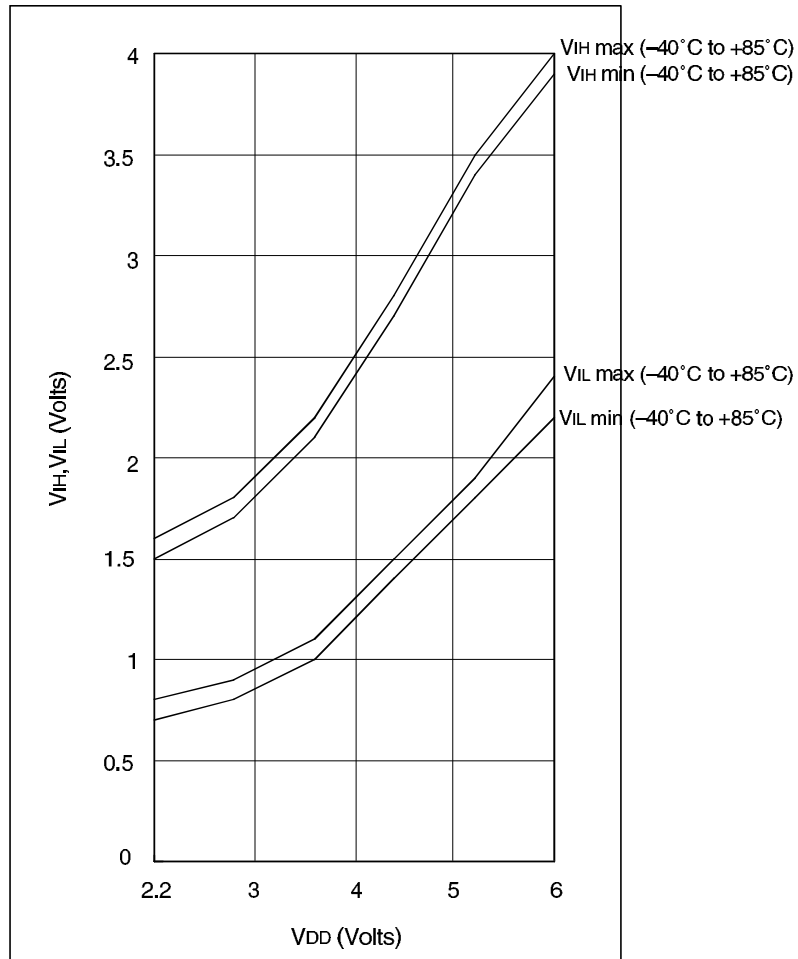


Figure J: Typical I_{STB} vs. V_{DD} watchdog enabled

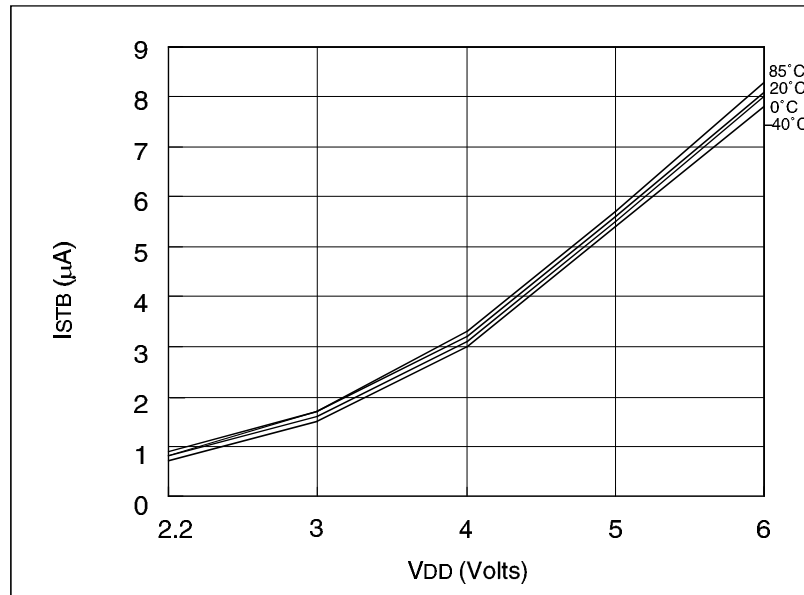


Figure K: Typical I_{STB} vs. V_{DD} watchdog disabled

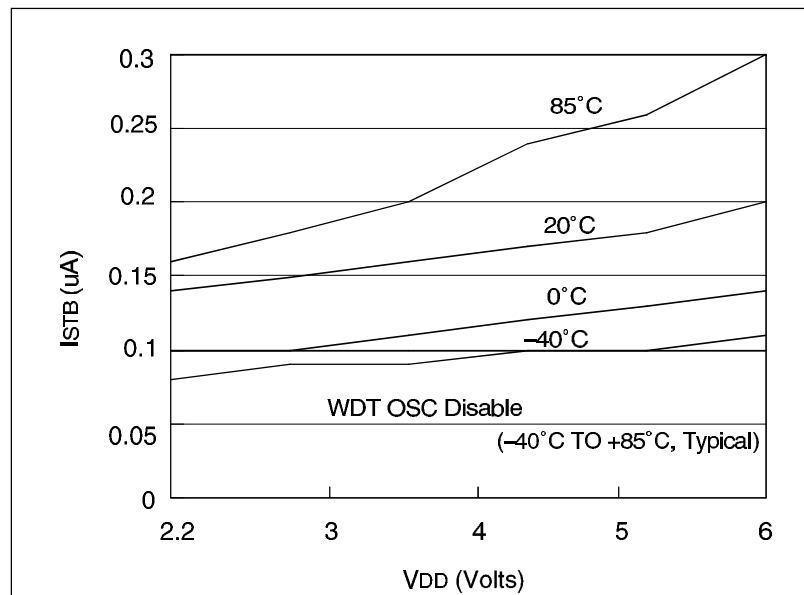
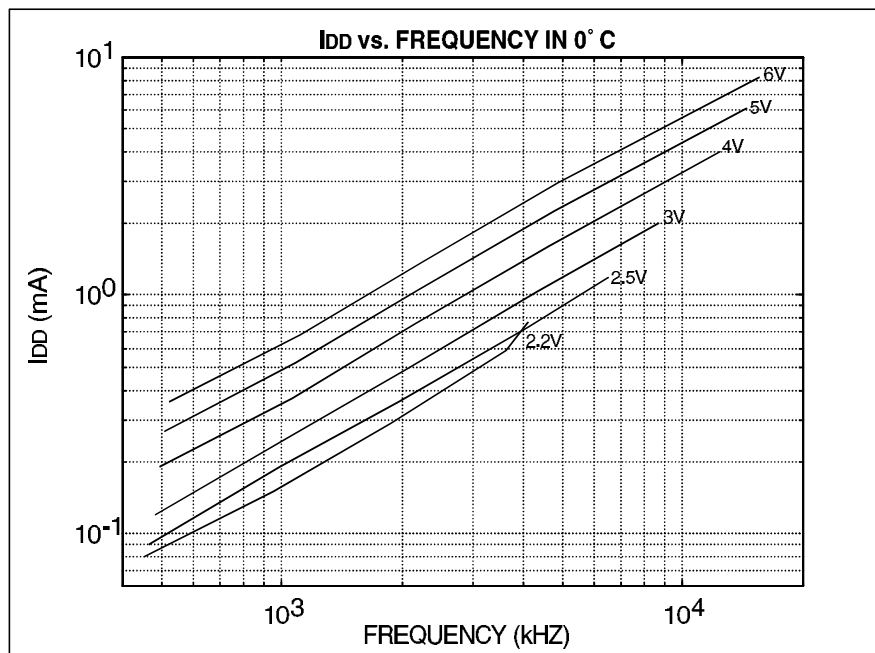
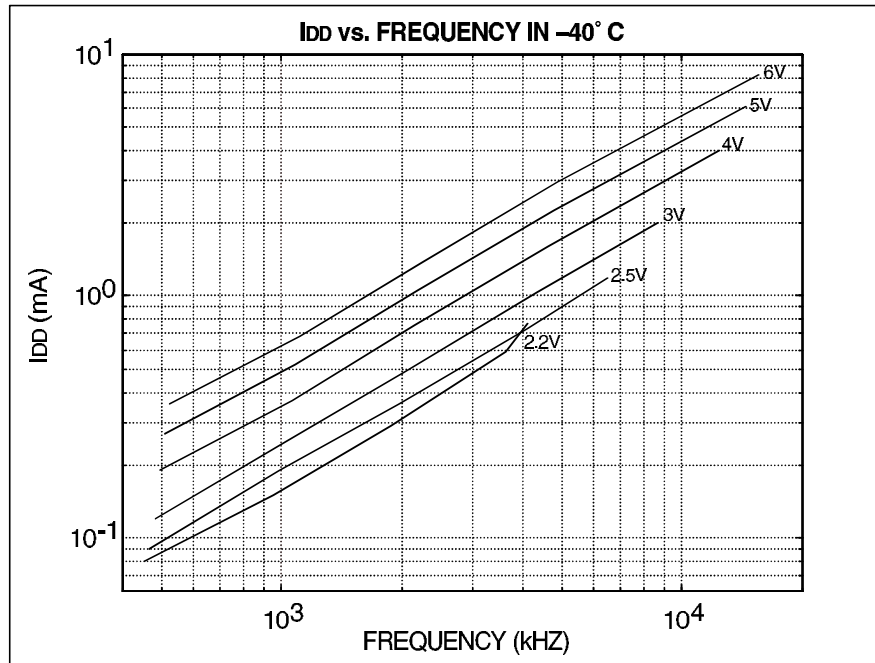


Figure L: Maximum I_{DD} vs. Frequency (external clock -40°C To 85°C)



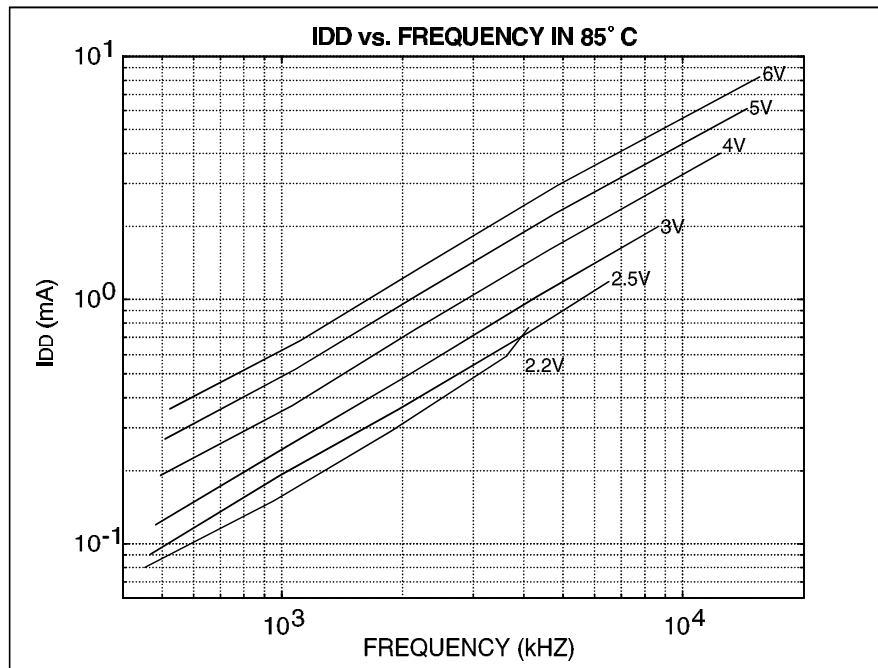
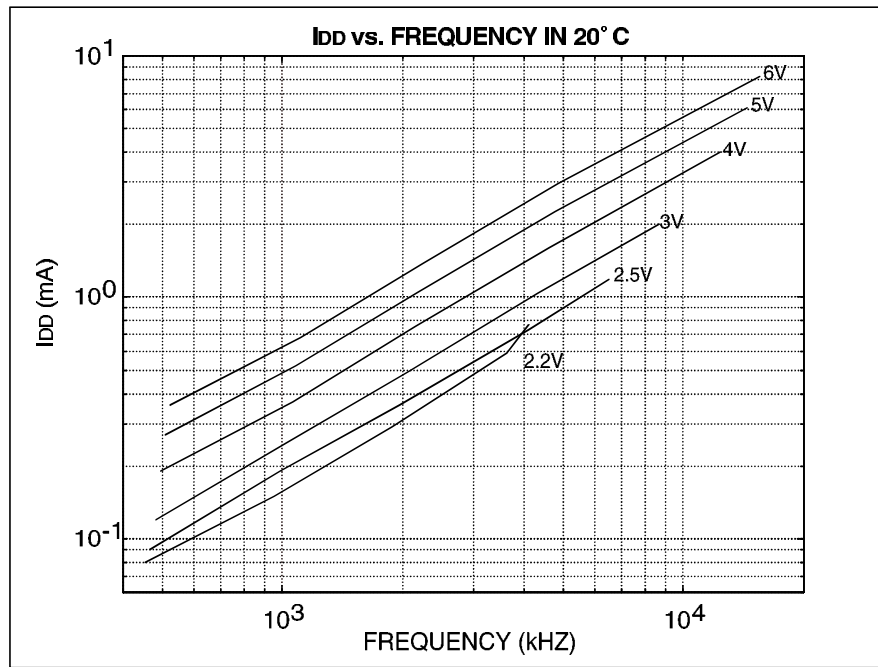


Figure M: Operating voltage-Operating frequency (crystal)

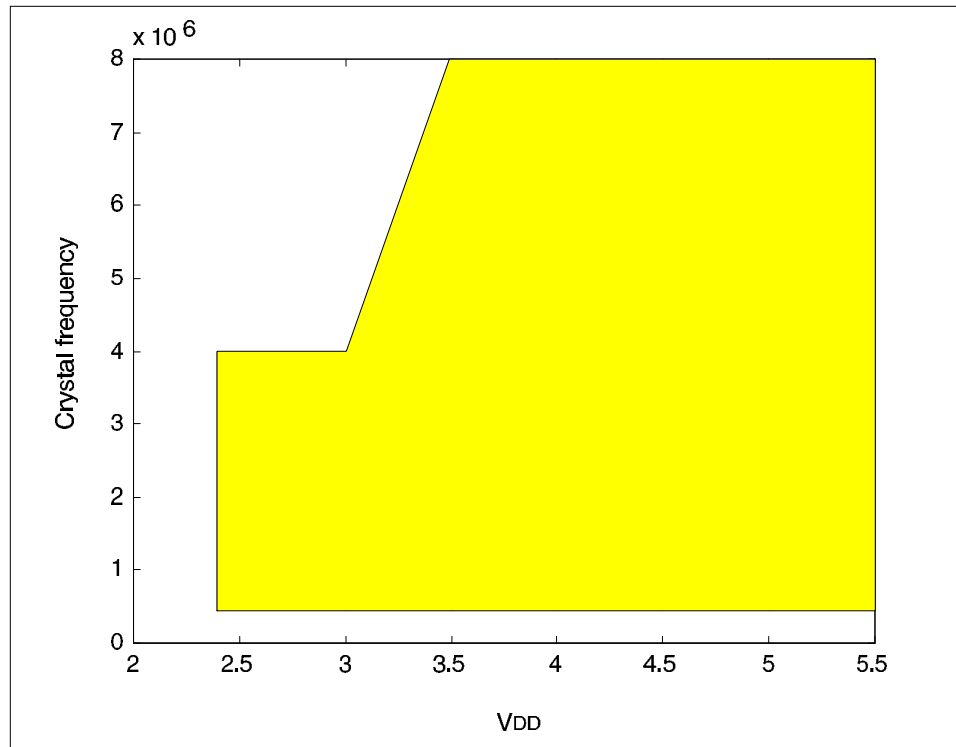
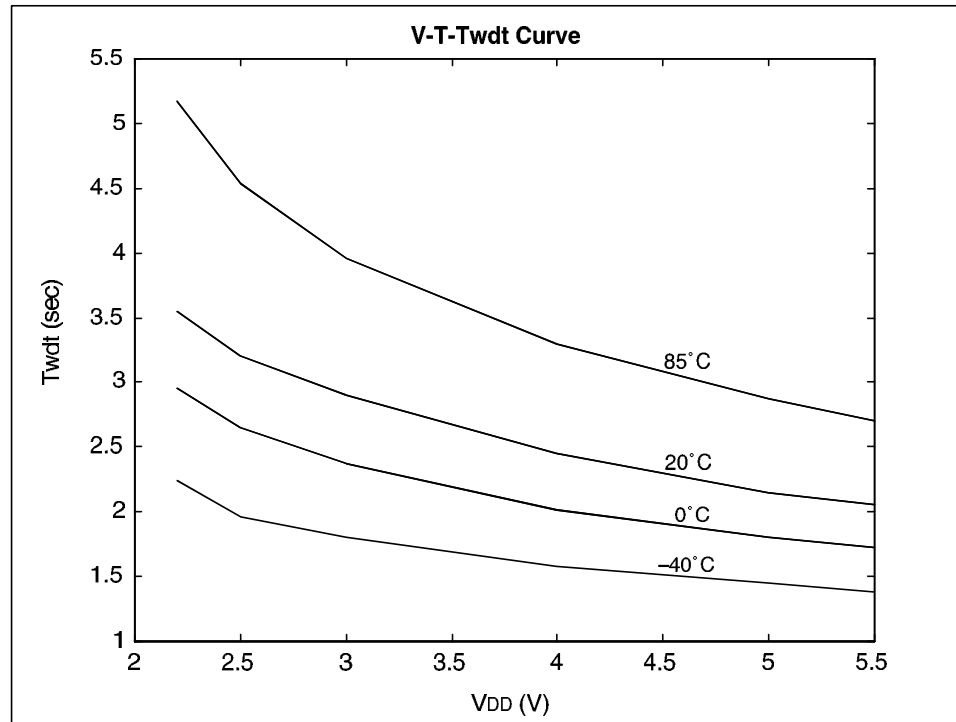


Figure N: Operating voltage vs. T_{WDT}



***Note :**

$T_{wdt}: 32768 \times (WDTOSC \text{ period})$

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